



# **Data Center design and efficiency; challenges today and in the future**

Michael K Patterson, PhD, PE  
Senior Power & Thermal Architect  
Eco-Technology Program Office  
Intel Architecture Group

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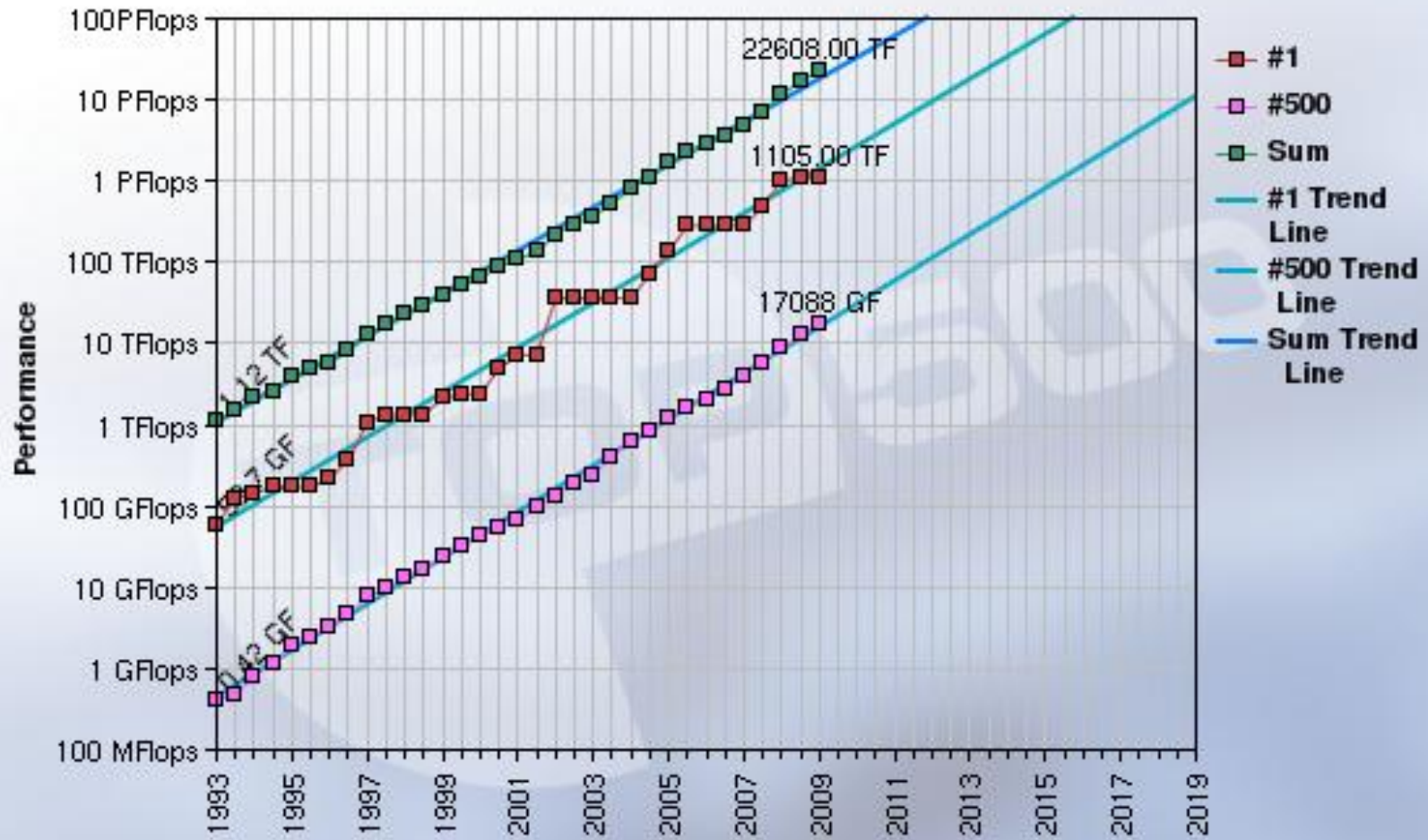
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## Projected Performance Development

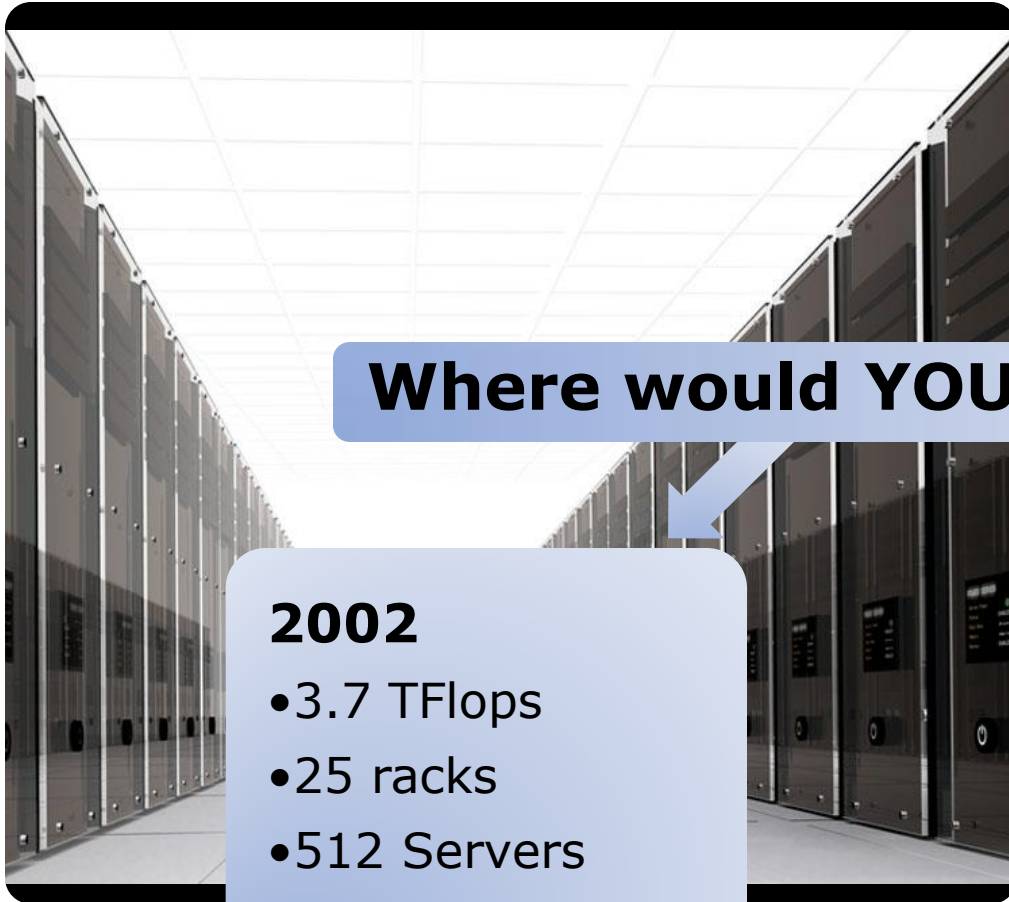


19/06/2009

<http://www.top500.org/>

# Moore's Law ...

## Alive and Well in the Data Center



**Where would YOU rather be?**

### **2002**

- 3.7 TFlops
- 25 racks
- 512 Servers
- 90 m<sup>2</sup>
- 128 kW



### **2007**

- 3.7 TFlops
- 1 rack
- 53 Servers
- 4 m<sup>2</sup>
- 21 kW

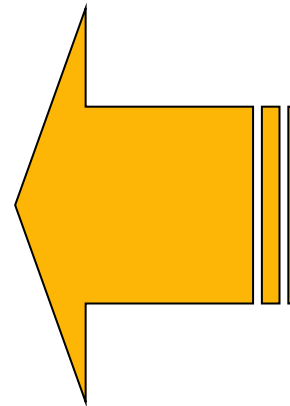
# But what does this mean to our HPC challenges?

*As we have commoditized the server, we have un-commoditized the data center.*

*This is NOT a "crisis", instead it's an **opportunity** to differentiate.*

*Those who apply the right planning and engineering will prosper, those who do not will suffer.*

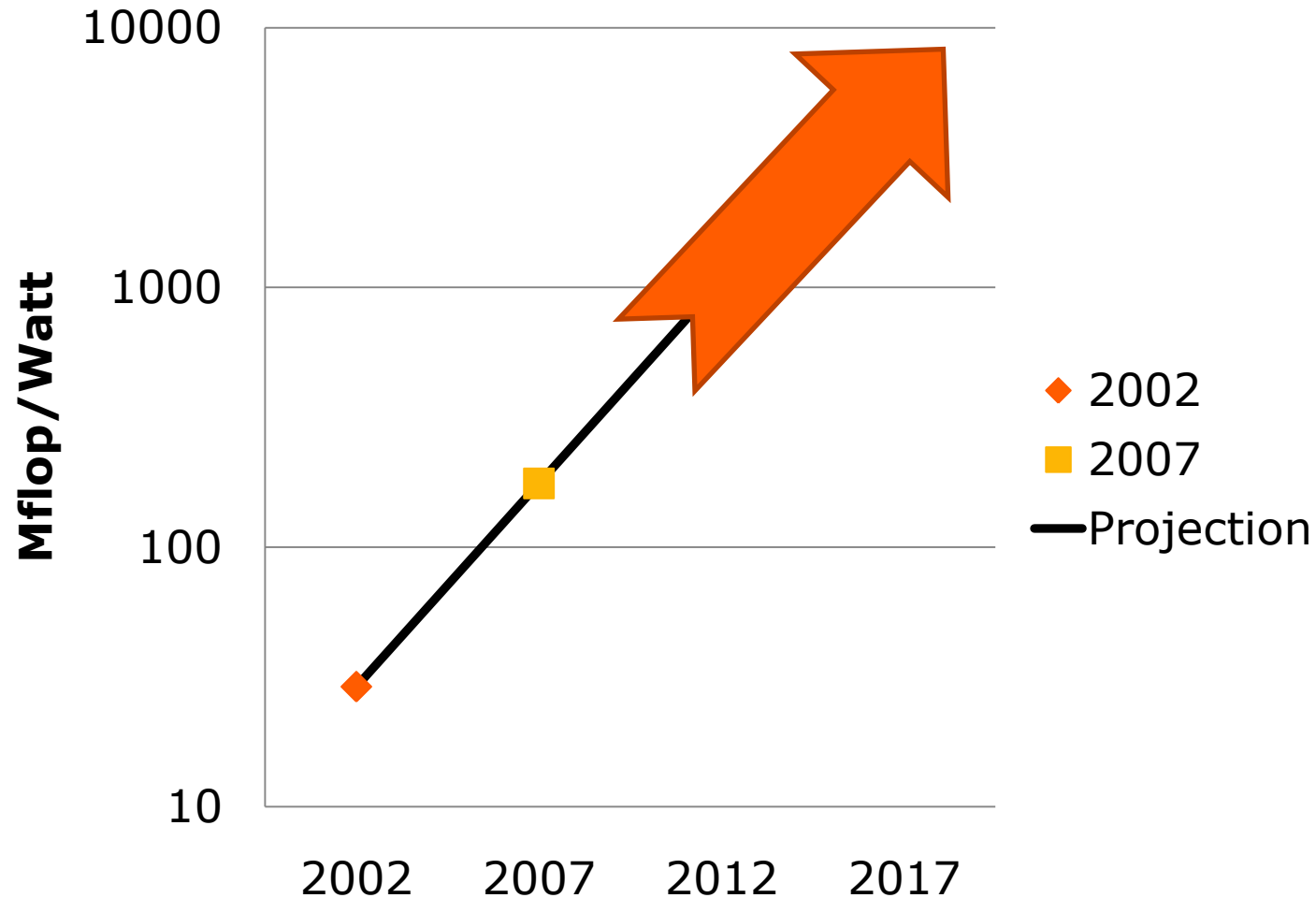
*Good engineering will allow higher density, lower TCO, and more space for more compute*



**2010**

- 6 TFlops
- 1 rack
- 64 Servers
- 4 m<sup>2</sup>
- 30 kW

# Extrapolations can be fun, *but dangerous!*



**An Exascale machine will take 120-150 MW unless we do something different, Intel currently working this challenge**

# A back of the envelope calculation.. (in other words not an Intel projection...but more a thought experiment)

$$2010 \Rightarrow \frac{1 \text{ petaflop}}{521 \text{ kW}}$$

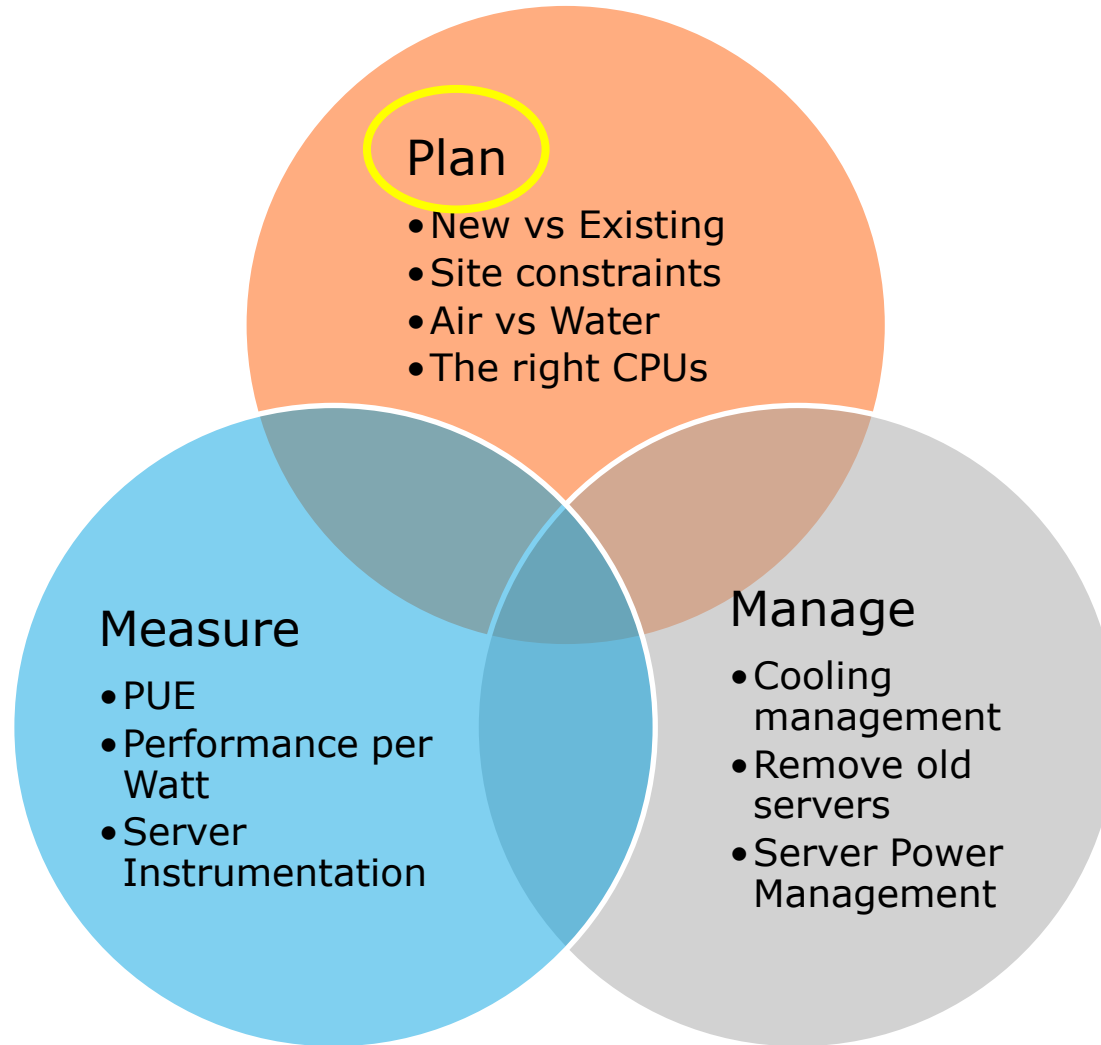
$$2008 \Rightarrow \frac{3.7 \text{ teraflops}}{21 \text{ kW}}$$

$$2002 \Rightarrow \frac{3.7 \text{ teraflops}}{128 \text{ kW}}$$

So at 0.10 CHF per kW-hr and a PUE of 2.0 the system will cost 900,000 CHF per year to run.

Each 0.1 reduction in PUE saves 45,000 CHF every year!

# How to succeed going forward?





# Technology to meet the HPC Challenges

**Westmere EP**

**Nehalem EX**

**Cost Sensitive**

**CPU Bound**

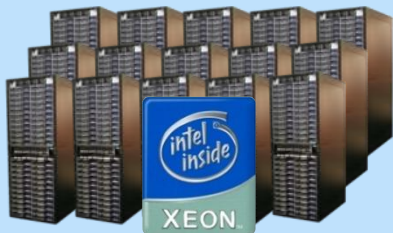
**Memory Bandwidth**

**Memory Capacity**

# EP Server Refresh: 2010

*Increasing your performance while decreasing your Energy cost*

2005



15 racks of  
Intel® Xeon®  
Single Core Servers

2010

Efficiency  
Refresh  
1:1



15 racks of  
Intel® Xeon® 5600  
Based Servers

Up to **15x**  
Performance

**8%** Annual Energy  
Costs Estimated  
Reduction

2006



5 racks of  
Intel® Xeon®  
Dual Core Servers

2010

Performance  
Refresh  
1:1



5 racks of  
Intel® Xeon® 5600  
Based Servers

Up to **5x**  
Performance

**10%** Annual  
Energy Costs  
Estimated Reduction

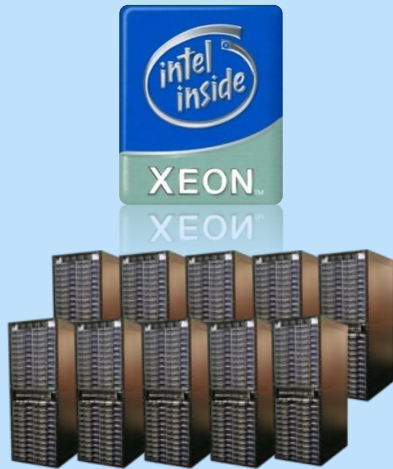
Source: Intel estimates as of Jan 2010. Performance comparison using SPECjbb2005 bops (business operations per second). Results have been estimated based on internal Intel analysis and are provided for informational purposes only. Any difference in system hardware or software design or configuration may affect actual performance. For detailed calculations, configurations and assumptions refer to the legal information slide in backup.



# Server Refresh Benefits

*(Single Core)*

2005



**100**  
**Intel® Xeon®**  
**Single Core**  
**4-socket**  
**Servers**

2010



**100**  
**Intel® Xeon®**  
**7500 Based**  
**Servers**

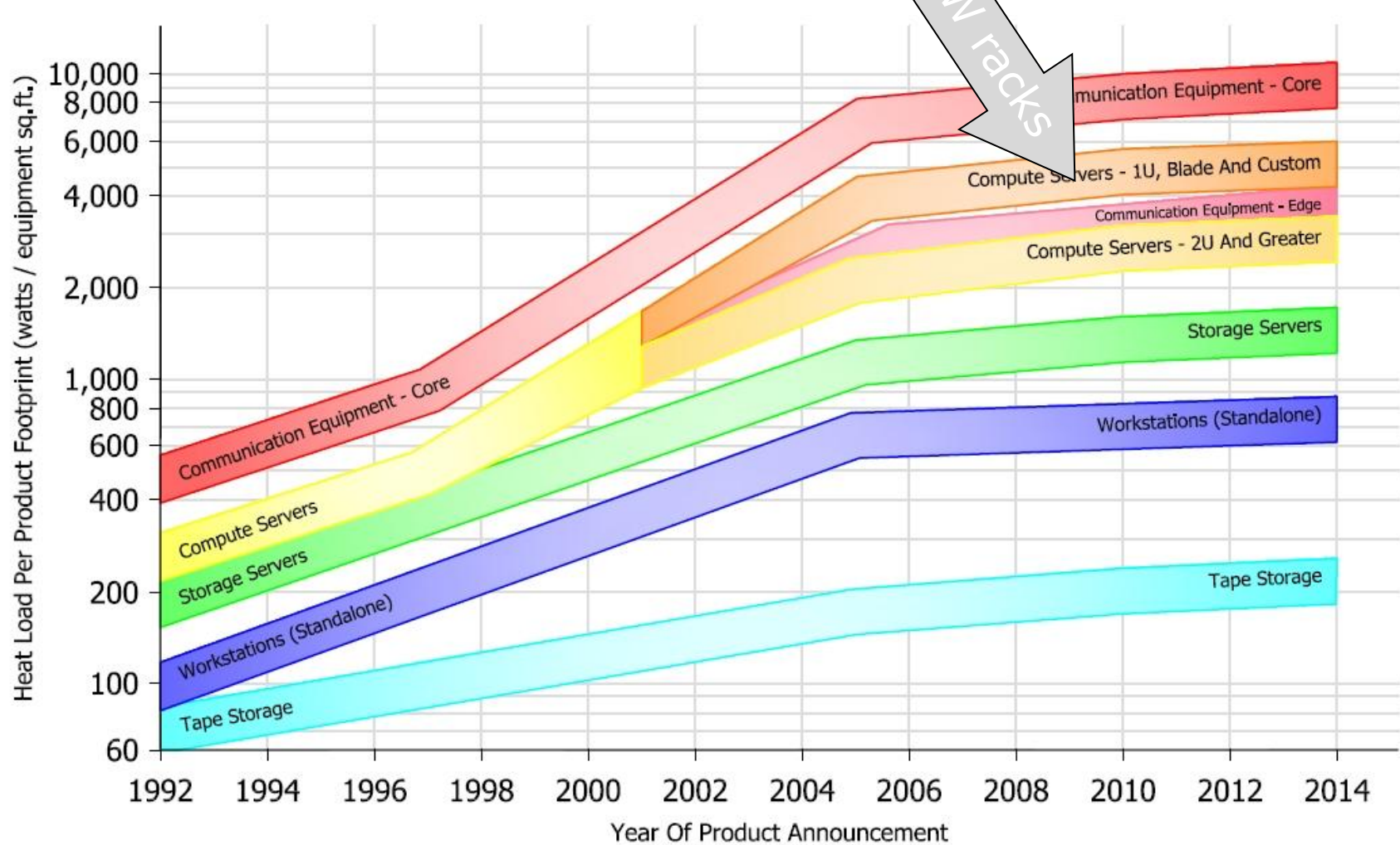
**Performance**  
**Refresh**  
**1:1**

**Estimated**  
**Up to**  
**20x**  
**Performance**

Source: Intel estimates as of February 2010. Performance comparison using internal workload. Results have been estimated based on internal Intel analysis and are provided for informational purposes only. Any difference in system hardware or software design or configuration may affect actual performance. For detailed calculations, configurations and assumptions refer to the legal information slide in backup.



# ASHRAE Roadmap for Density

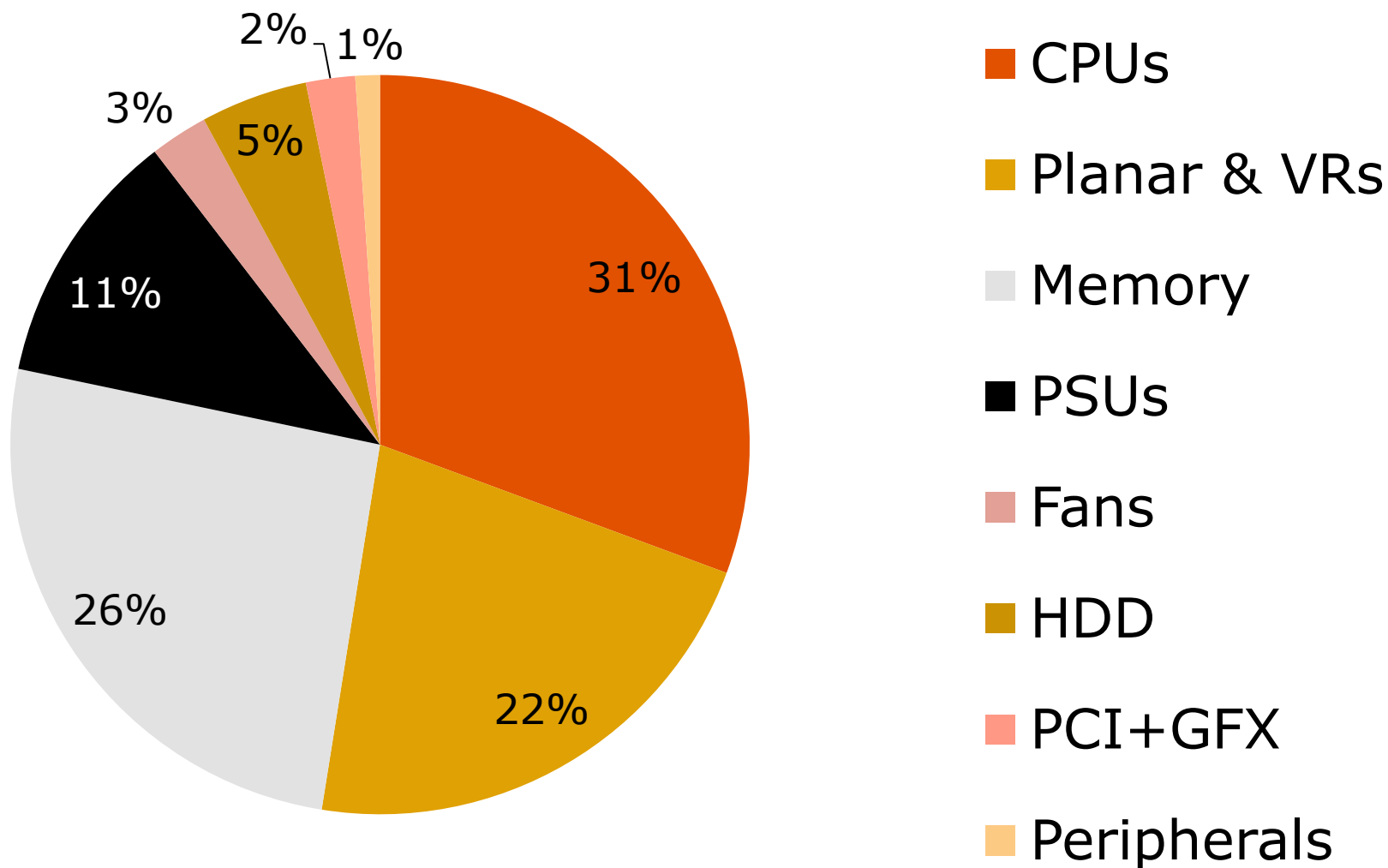


# But we are heading for liquid cooling, aren't we?

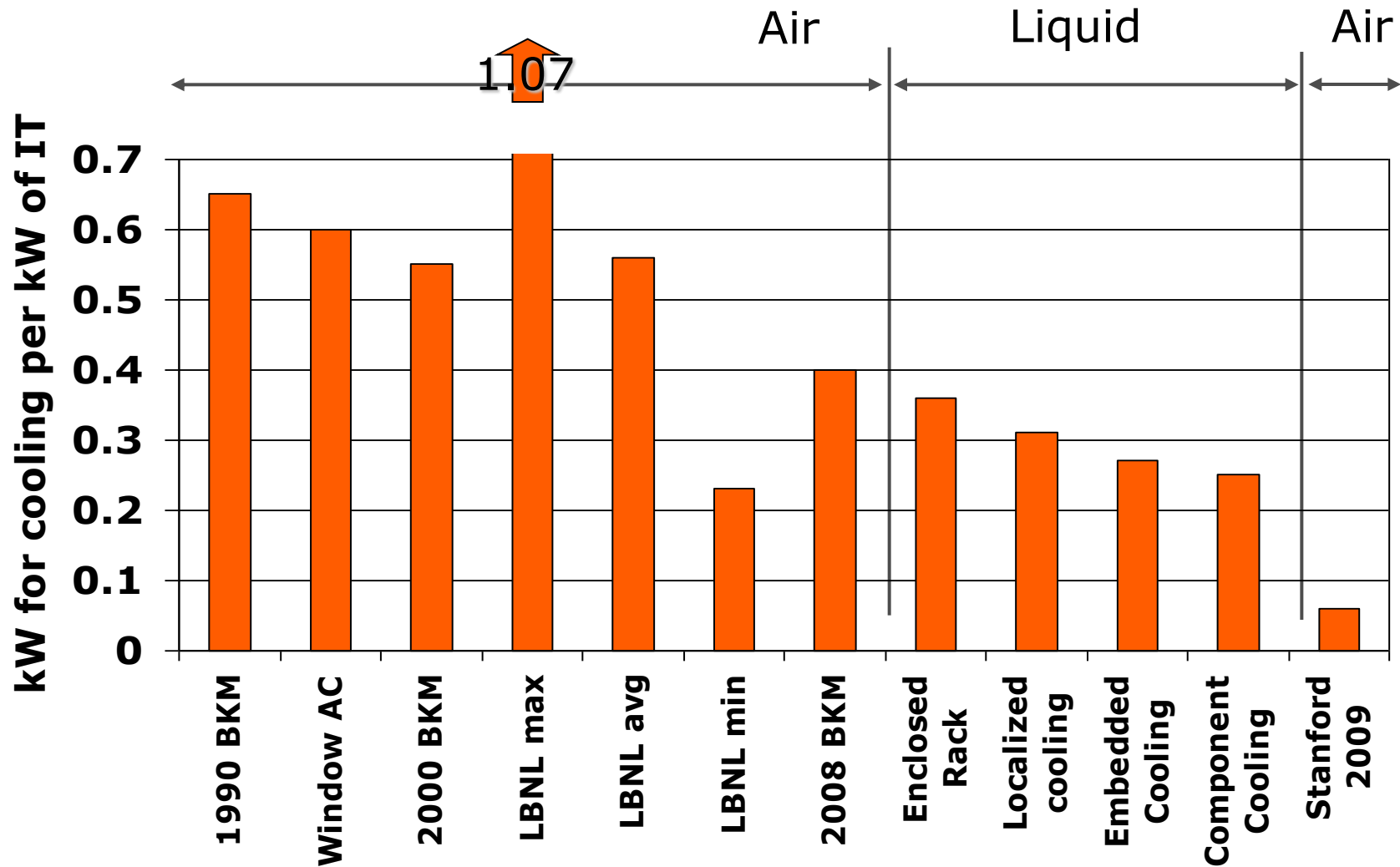


- Only maybe...
- Consider what we are liquid-cooling? Rack, server, component?
- Consider TCO
  - Different answer for different sites

# Typical Platform Power Distribution-HPC



# Cooling overhead by technology



Source: compilation of data from LBNL, Liebert, IDC, Sears, Intel





# Scientific Research Computing Facility Stanford University



Chiller-less data center,  
Cooling overhead – 6%



# Cooling Limit *very rough* estimates +/-

<u>Cooling Architecture</u>	<u>Limits</u>	<u>Comments</u>
Open data center	4 kW	Least efficient
Hot aisle/cold aisle	8-12 kW	Requires specific layouts for higher end
Cold aisle containment	30 kW	Best for legacy DCs
Hot aisle containment or chimney cabinets	30 kW	Best for new construction
Liquid cooled rack enclosure	35 kW	Ideal for legacy DCs with limited airflow
Liquid rear doors	15-30 kW	Can make rack room-neutral
In row coolers	20-35 kW	Space implications but rack independent
Close coupled coolers	10-25 kW	Overhead has space advantages
CPU liquid cooling	80 kW	Caution! must we cool the rest with air?
Integrated liquid cooling	100 kW	Benefits in Interconnect

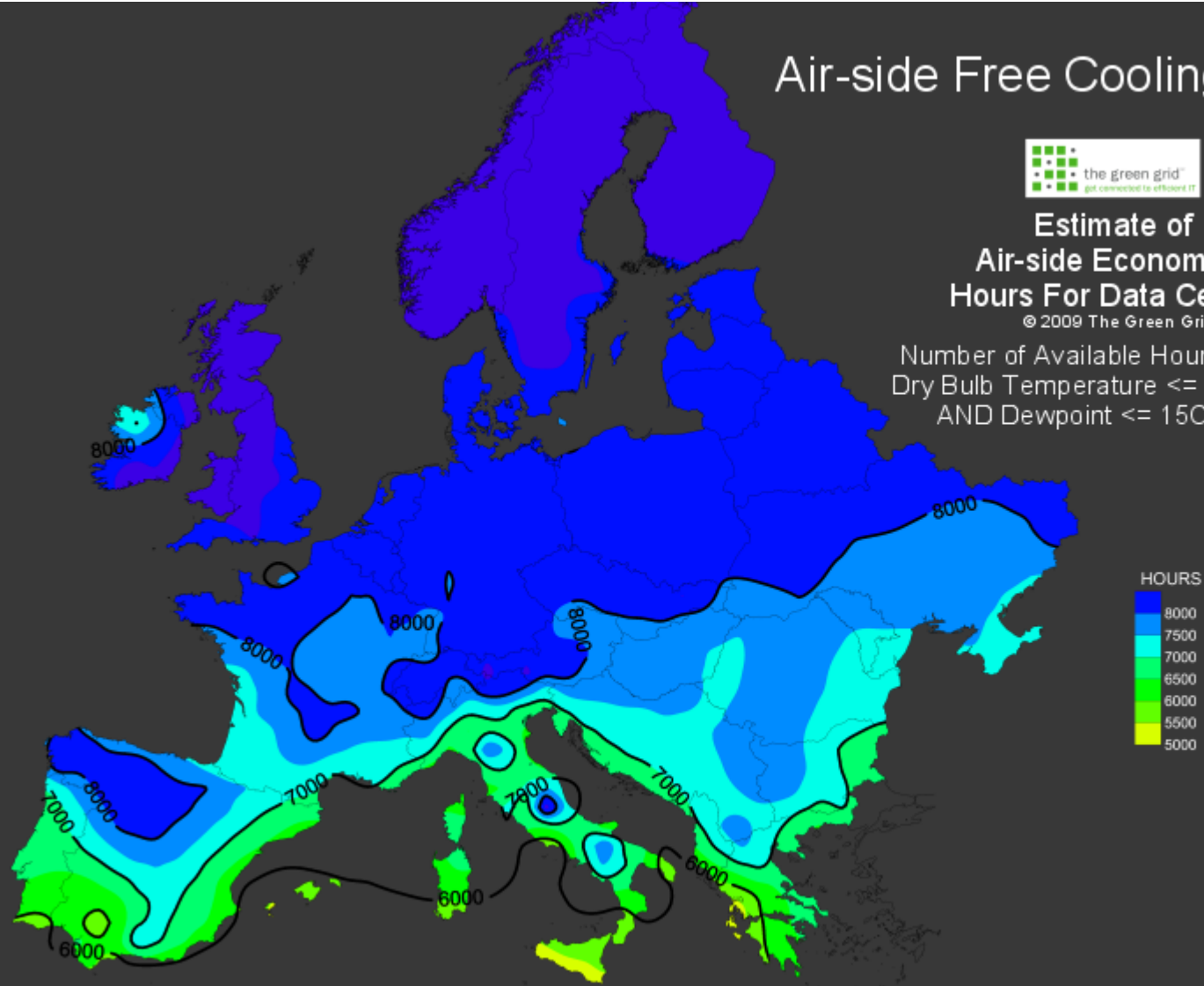
# Air-side Free Cooling Map



## Estimate of Air-side Economizer Hours For Data Centers

© 2009 The Green Grid

Number of Available Hours Where:  
Dry Bulb Temperature  $\leq 27^{\circ}\text{C}$  ( $81^{\circ}\text{F}$ )  
AND Dewpoint  $\leq 15^{\circ}\text{C}$  ( $59^{\circ}\text{F}$ )



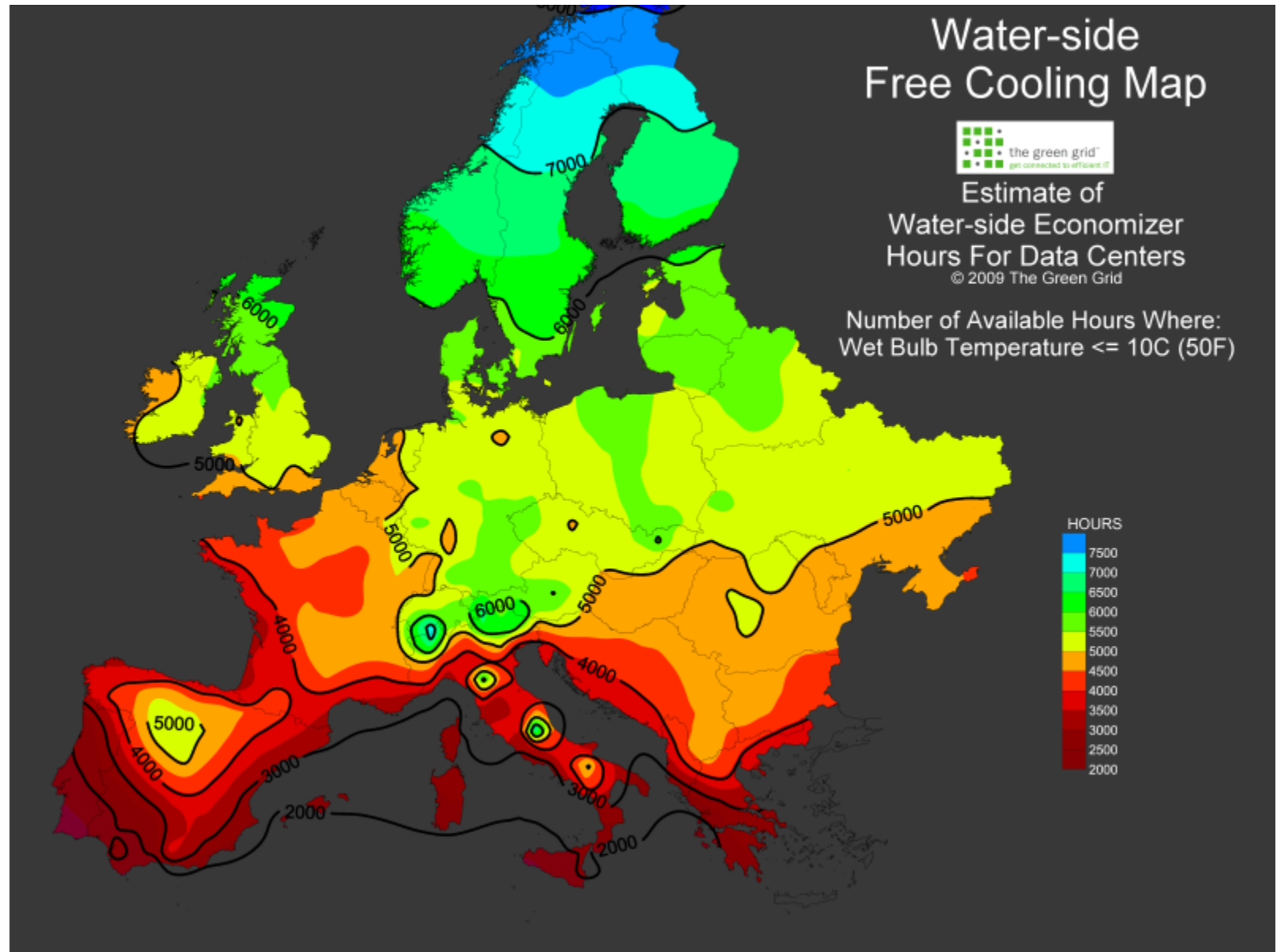
# Water-side Free Cooling Map



Estimate of  
Water-side Economizer  
Hours For Data Centers

© 2009 The Green Grid

Number of Available Hours Where:  
Wet Bulb Temperature  $\leq 10\text{C}$  (50F)





## Free-Cooling Estimated Savings

COUNTRY: SWITZERLAND

CITY: Bern, LSZB

DEGREES IN: ☐ FAHRENHEIT☒ CELSIUSALLOW MIXING OF SUPPLY AND RETURN AIR ☒ALLOW HUMIDIFICATION ☒

	MAX LIMIT	MIN LIMIT
DRYBULB TEMP THRESHOLD (DEG): ?	<input type="text" value="27.0"/>	<input type="text" value="NONE"/>
DEWPOINT TEMP THRESHOLD (DEG): ?	<input type="text" value="15.0"/>	<input type="text" value="NONE"/>
REL. HUMIDITY THRESHOLD (%): ?	<input type="text" value="NONE"/>	
DESIRED CHILLED WATER TEMP (DEG): ?	<input type="text" value="13.0"/>	
COOLING SYSTEM APPROACH TEMP (DEG): ?	<input type="text" value="3.0"/>	

CALCULATE

RESET FORM

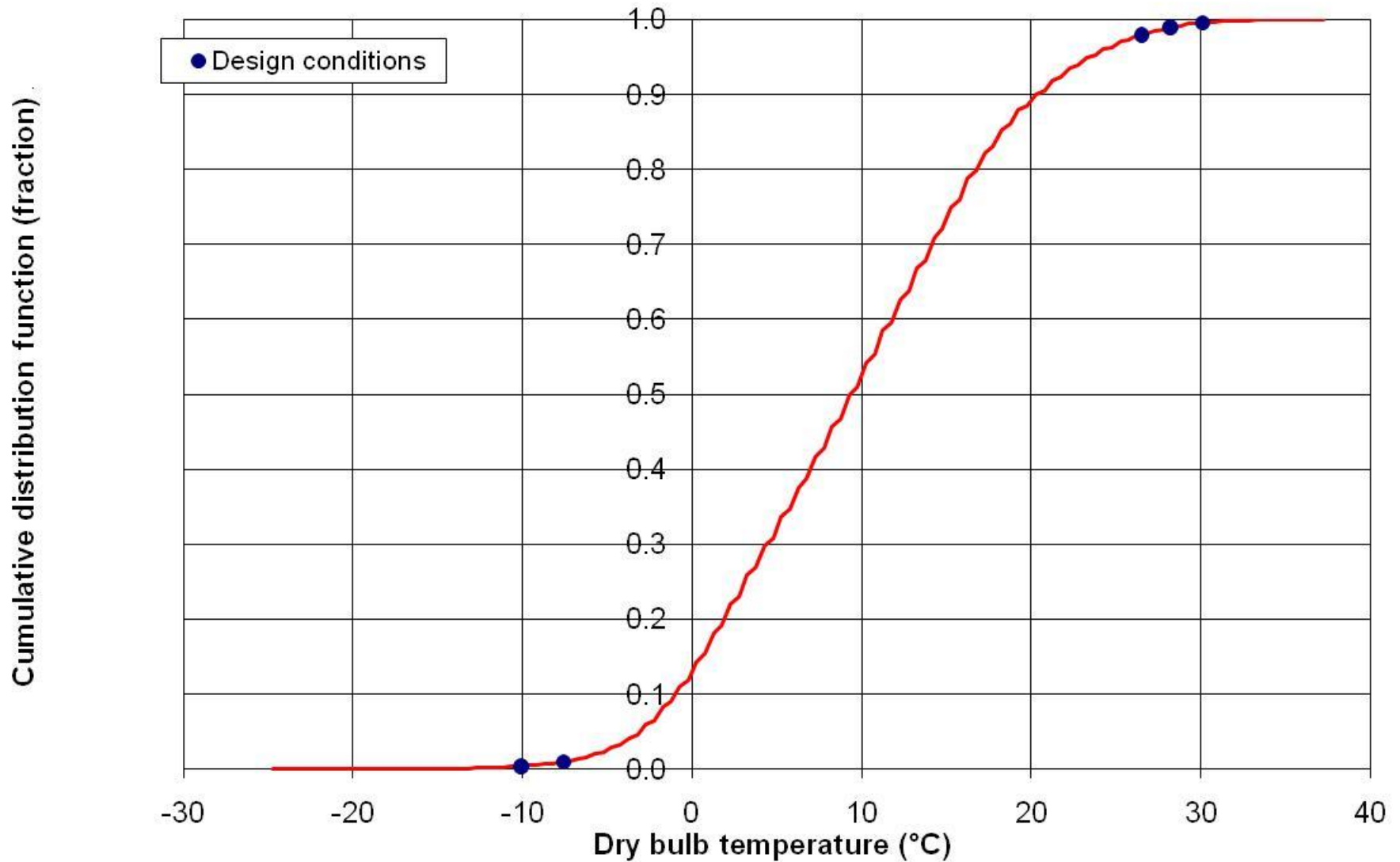
HELP

[Comment Now](#)

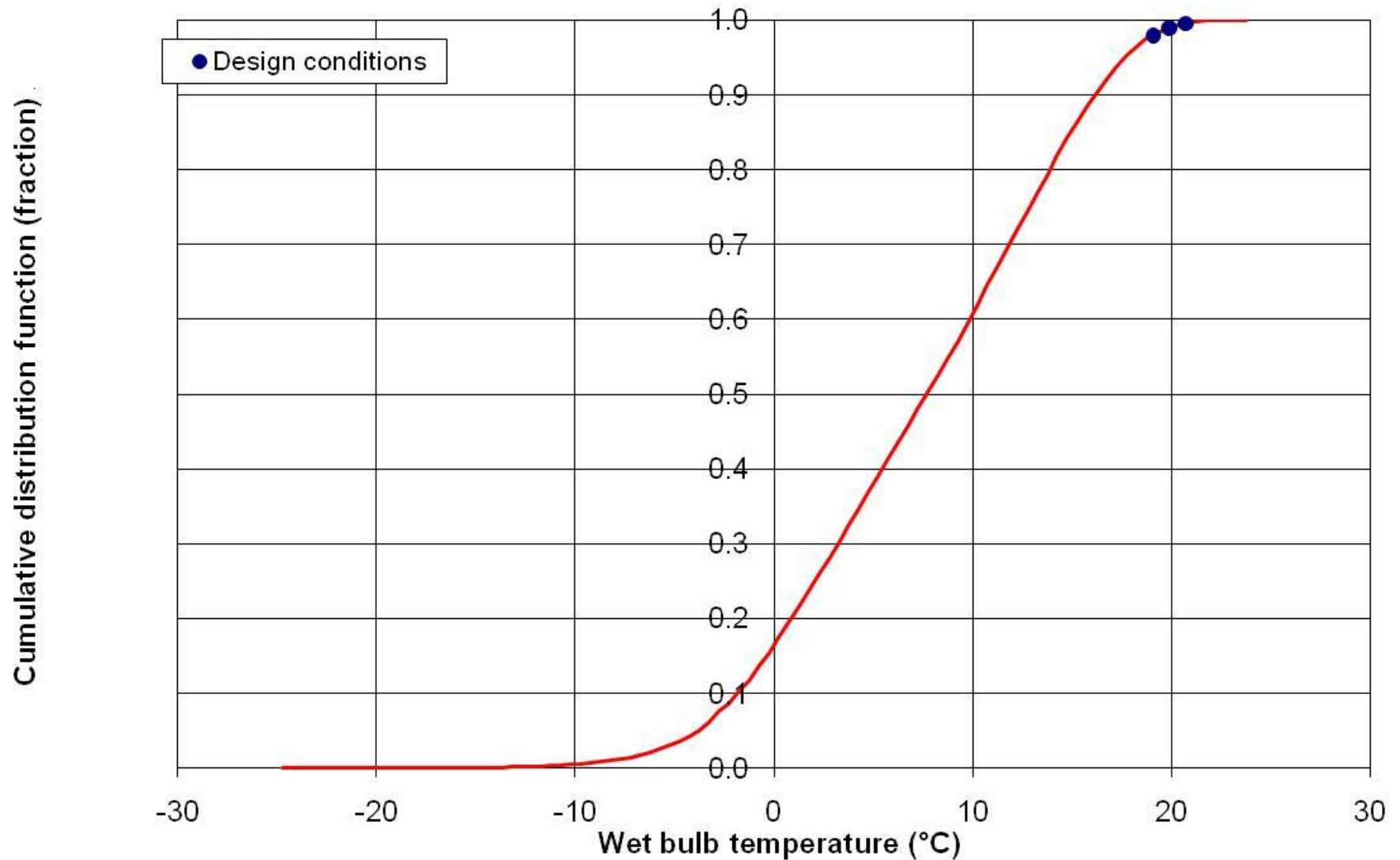
DATA CENTER IT POWER (kW): ?	<input type="text" value="1000"/>	
POWER USAGE EFFECTIVENESS (PUE): ?	<input type="text" value="1.6"/>	
TOTAL FACILITY POWER (kW): ?	<input type="text" value="1600"/>	
OVERHEAD POWER (kW): ?	<input type="text" value="600"/>	
PERCENT OF OVERHEAD POWER FOR COOLING SYSTEM (%): ?	<input type="text" value="80"/>	% <input type="text" value="480"/> kW
PERCENT OF COOLING SYSTEM POWER FOR CHILLER (%): ?	<input type="text" value="40"/>	% <input type="text" value="192"/> kW
PERCENT OF COOLING SYSTEM POWER FOR TOWER (%): ?	<input type="text" value="40"/>	% <input type="text" value="192"/> kW
PERCENT OF COOLING SYSTEM POWER FOR PUMPS/FANS (%): ?	<input type="text" value="20"/>	% <input type="text" value="96"/> kW
PERCENT OF OVERHEAD POWER FOR POWER LOSSES and LIGHTING (%): ?	<input type="text" value="20"/>	% <input type="text" value="120"/> kW
ELECTRIC COST (€ <input type="text" value=""/> per kWh) ?	<input type="text" value="0.132"/>	

HOURS MEETING CRITERIA FOR FREE-AIR COOLING: ESTIMATED SAVINGS USING FREE-AIR COOLING: HOURS MEETING CRITERIA FOR WATER SIDE ECONOMIZER: ESTIMATED SAVINGS USING WATER SIDE ECONOMIZER:

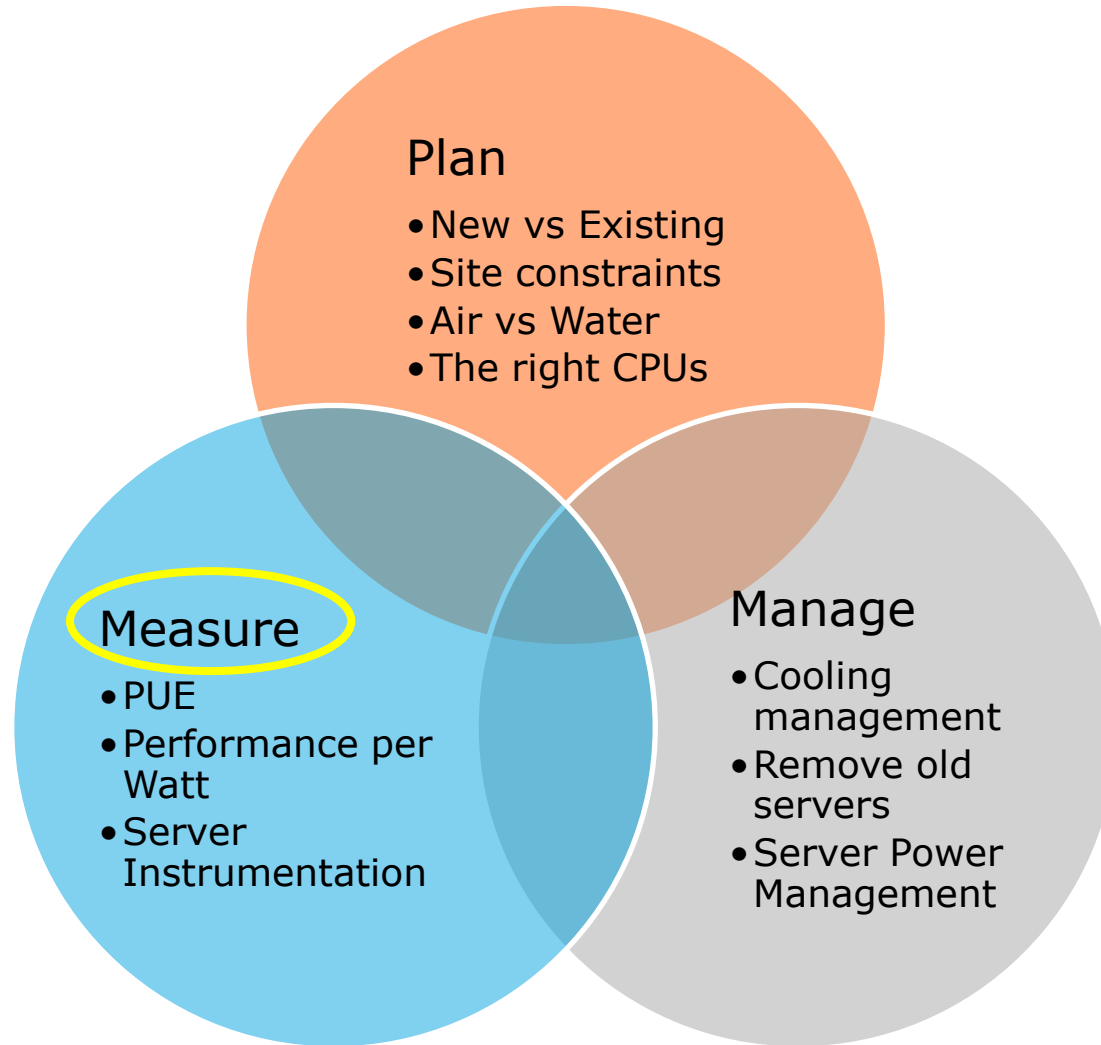
Dry bulb temperature cumulative distribution function - Annual  
ZURICH-KLOTEN, Switzerland (066700)



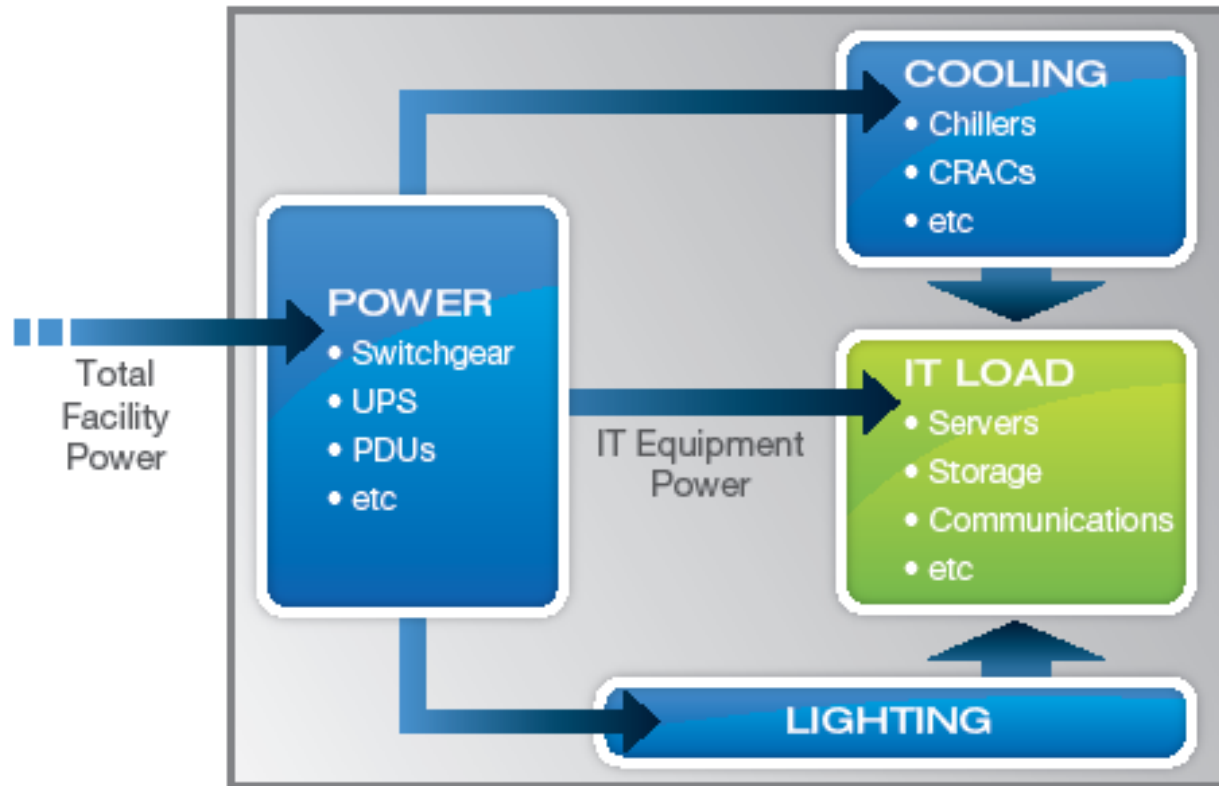
Wet bulb temperature cumulative distribution function - Annual  
ZURICH-KLOTEN, Switzerland (066700)



# How to succeed going forward?



## PUE: Power Usage Effectiveness



$$\text{PUE} = \frac{\text{Total Facility Power}}{\text{IT Equipment Power}}$$

$$\text{DCIE} = \frac{1}{\text{PUE}} \times 100\%$$

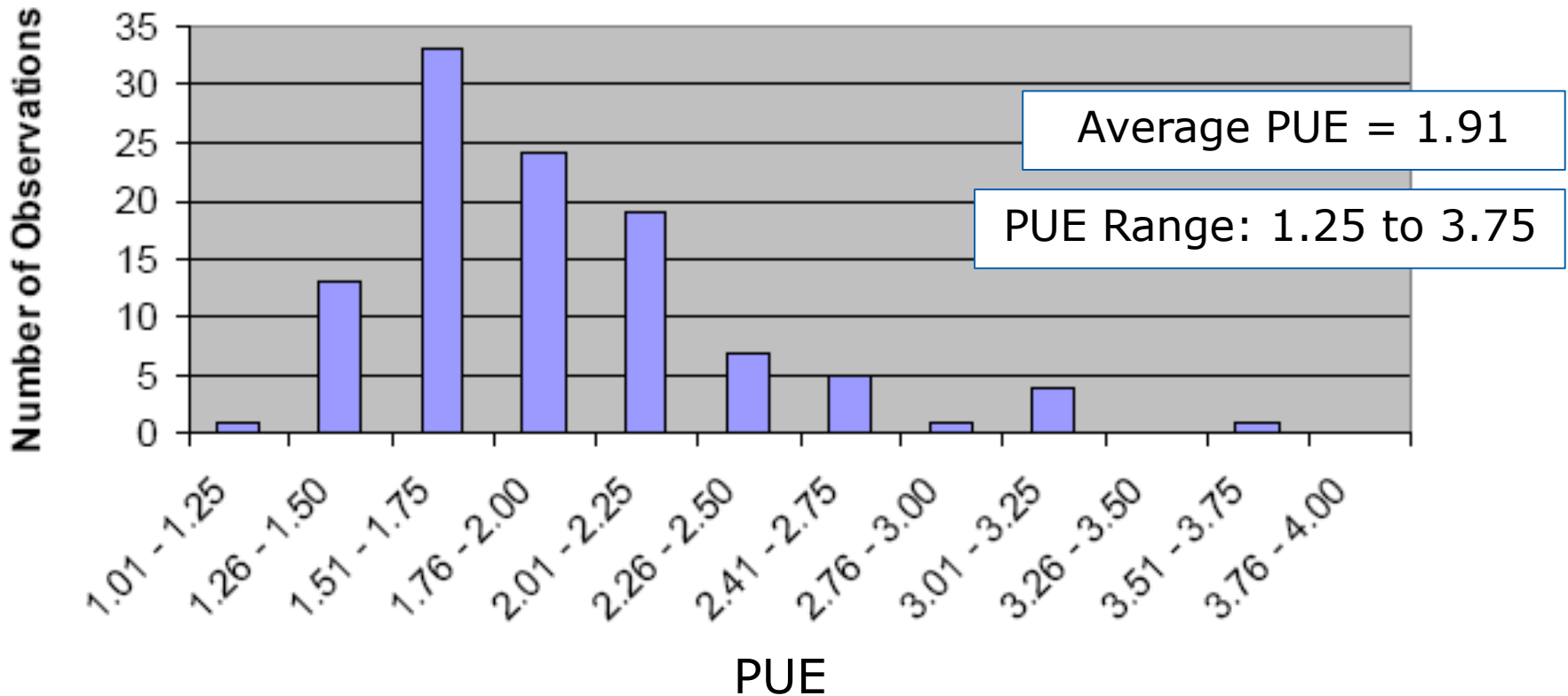


# Data Center Efficiency

$$\text{PUE} = \frac{\text{Total Facility Power}}{\text{IT Equipment Power}}$$

- Expressed as Power Usage Effectiveness (PUE)
  - Ideal PUE = 1.0
- Typical data center today = 2.0 → 3.0+
- Best Practices ~1.5
- World Class ~1.2-1.3

# EPA Energy Star for Data Centers first years results....



# What to do? State of the art needed today for better PUEs

## • Cooling

- Airflow management
- Liquid cooled racks or rear doors
- Close-coupled cooling
- Economizers
  - Air, water, evaporative
- ASHRAE Extended Envelope\*
  - 18-27C
  - 5.5-15C dewpoint
- Airflow management

## • Power

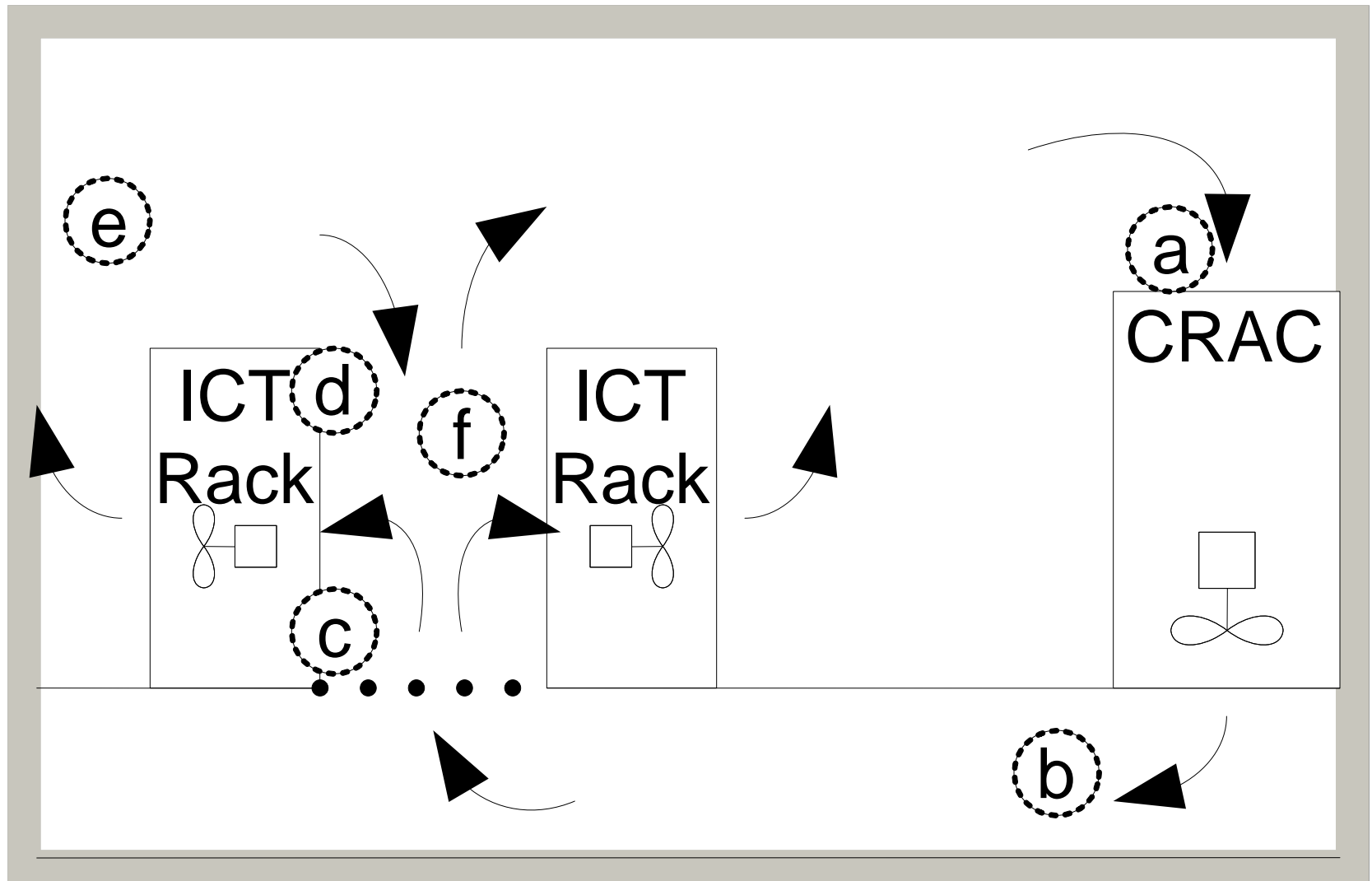
- High efficiency power architecture, primarily spend the money for better components
  - Climate Savers Computing Initiative
- 208Vac or 230Vac
- 480/277 only in the very high end
- Smart UPS (only on what you need)
- DC power and HPC don't align due to limited UPS use

It's really all about good engineering!

\*[http://tc99.ashraetcs.org/documents/ASHRAE\\_Extended\\_Environmental\\_Envelope\\_Final\\_Aug\\_1\\_2008.pdf](http://tc99.ashraetcs.org/documents/ASHRAE_Extended_Environmental_Envelope_Final_Aug_1_2008.pdf)

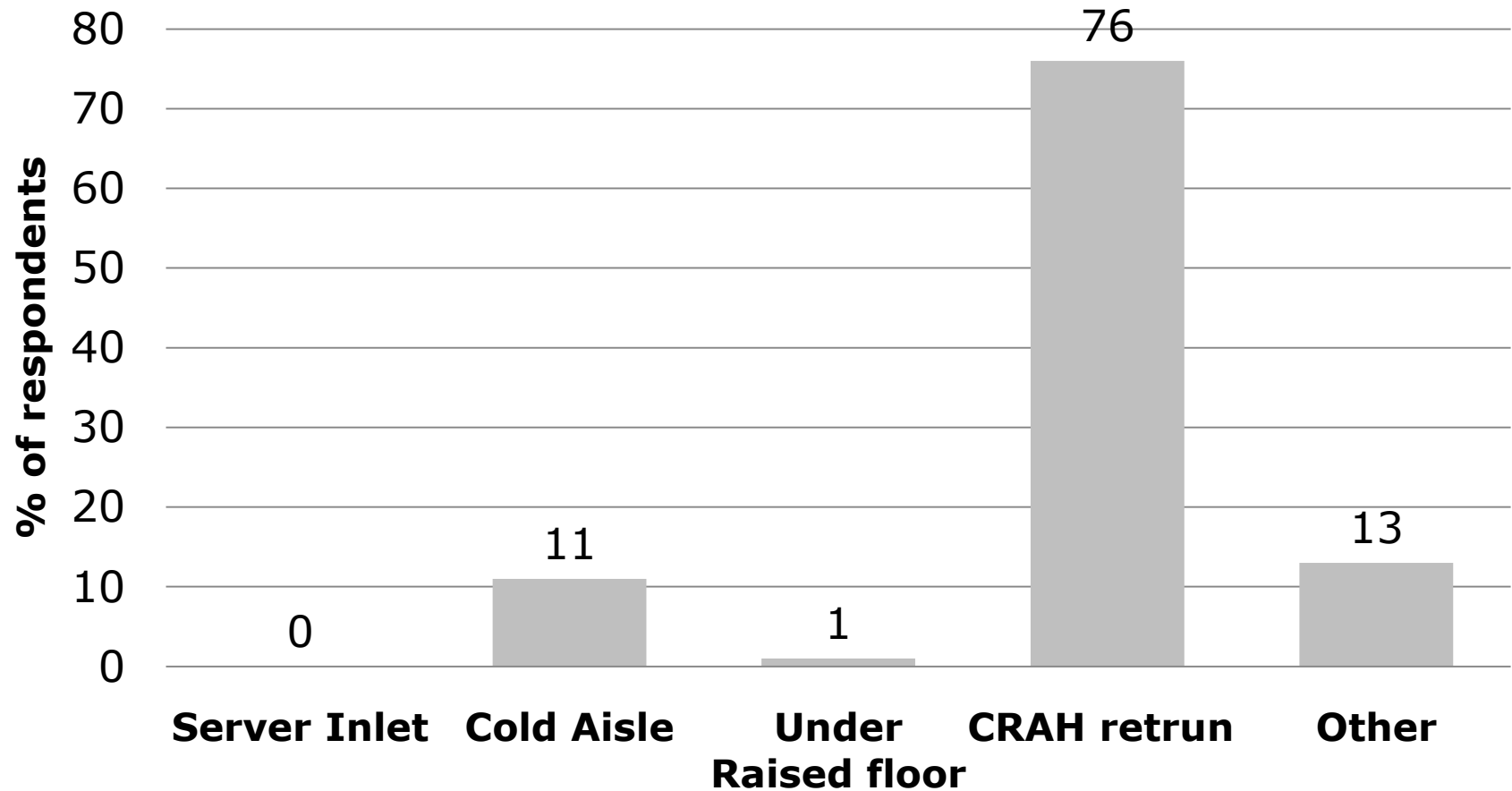


# Typical DC & control strategies



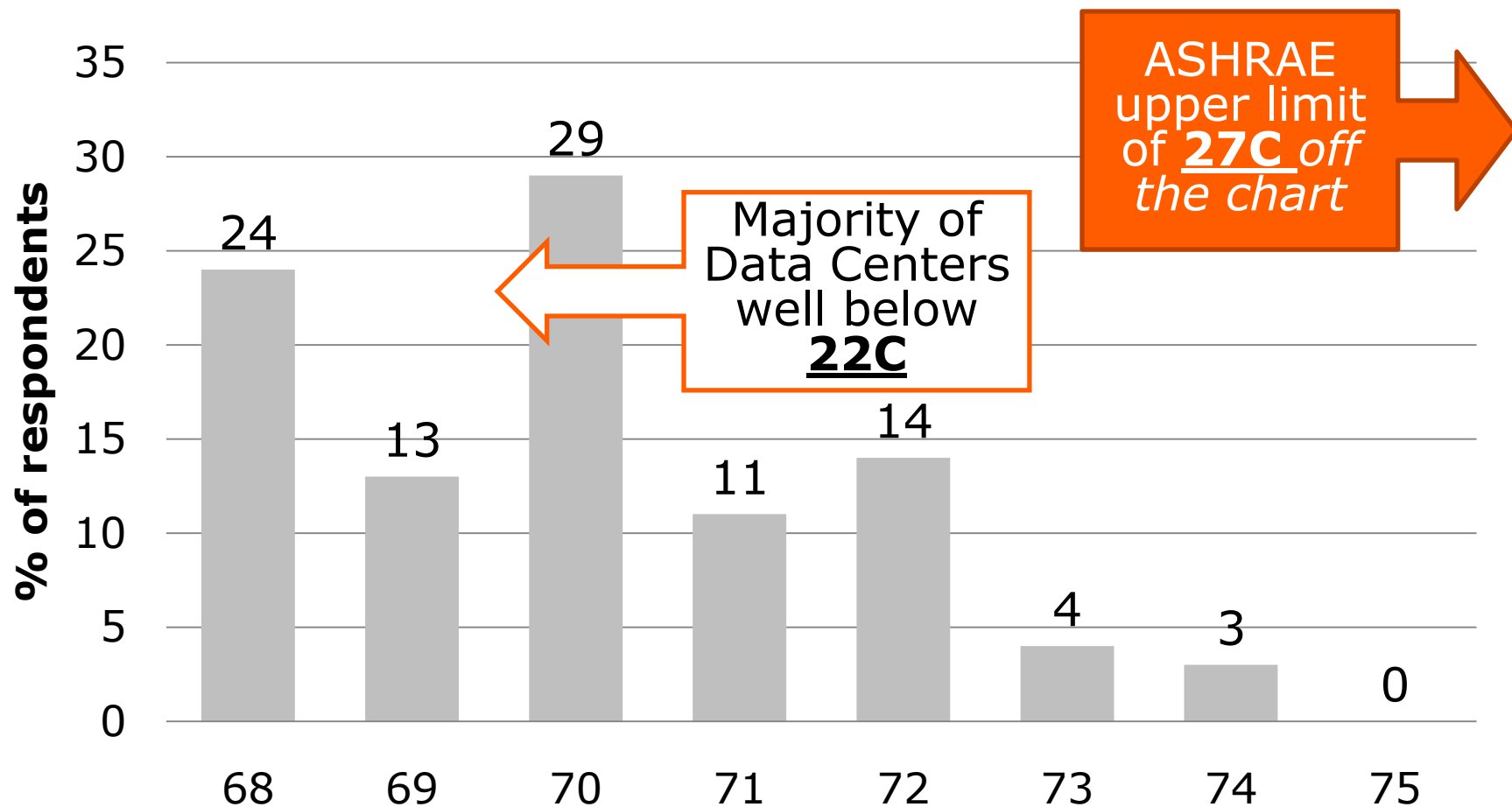
# CRAH/CRAC Set-Point Location

(from a recent Liebert DCUG survey)



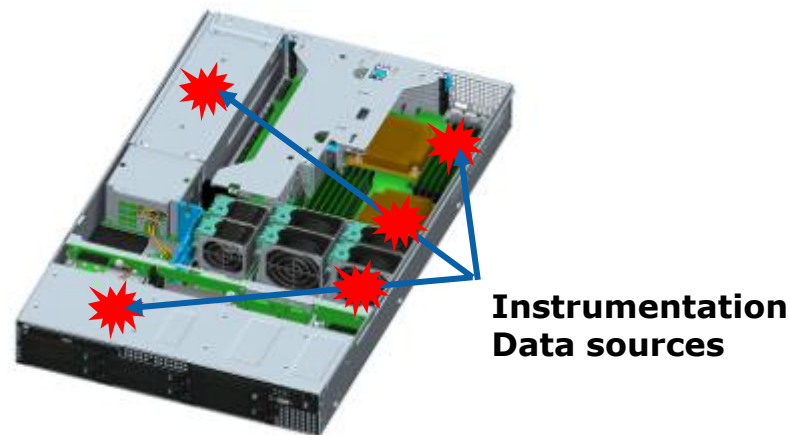
# CRAH/CRAC Set-Point Values °F

(from a recent Liebert DCUG survey)



# Server Instrumentation: Your System Efficiency Control Panel

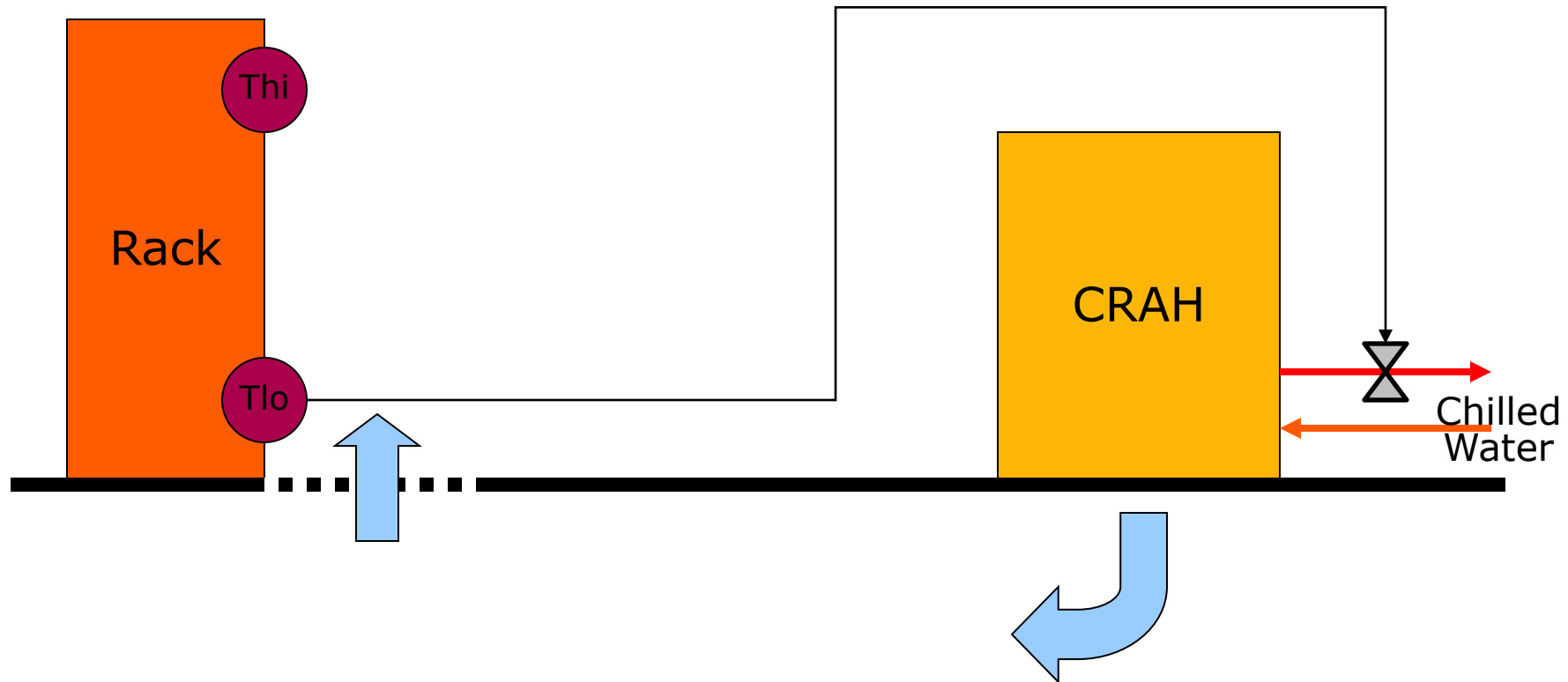
- Instrumentation allows a device to report data about itself and provides ability to toggle control
- Server instrumentation today controls:
  - System power
  - Temperature
  - P & T states
  - Variable speed tachometer
  - Perf counters, ACPI, OSPM, and more



**Instrumentation Provides Data Foundation  
For Server Management**

# Logical Controls Architecture

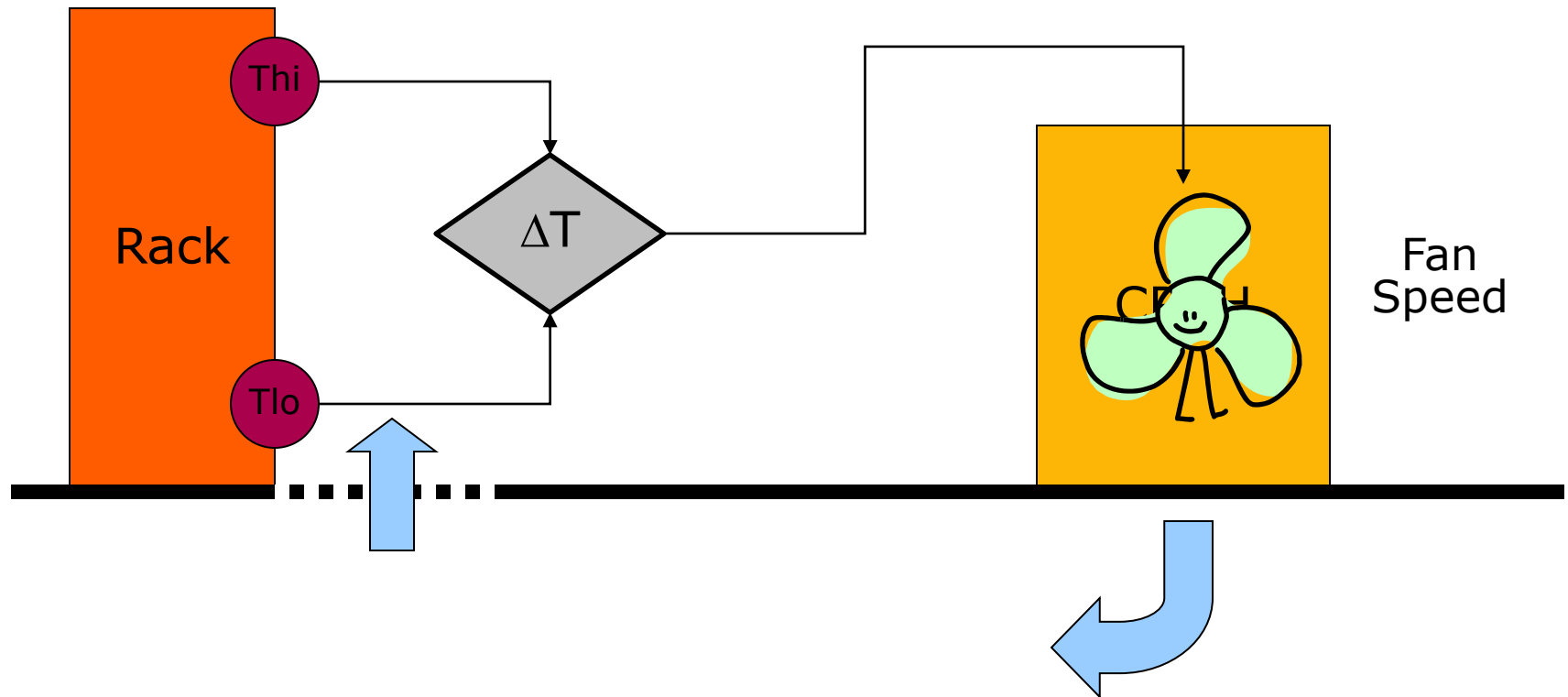
## Chilled Water Valve Position = $f(T_{lo})$





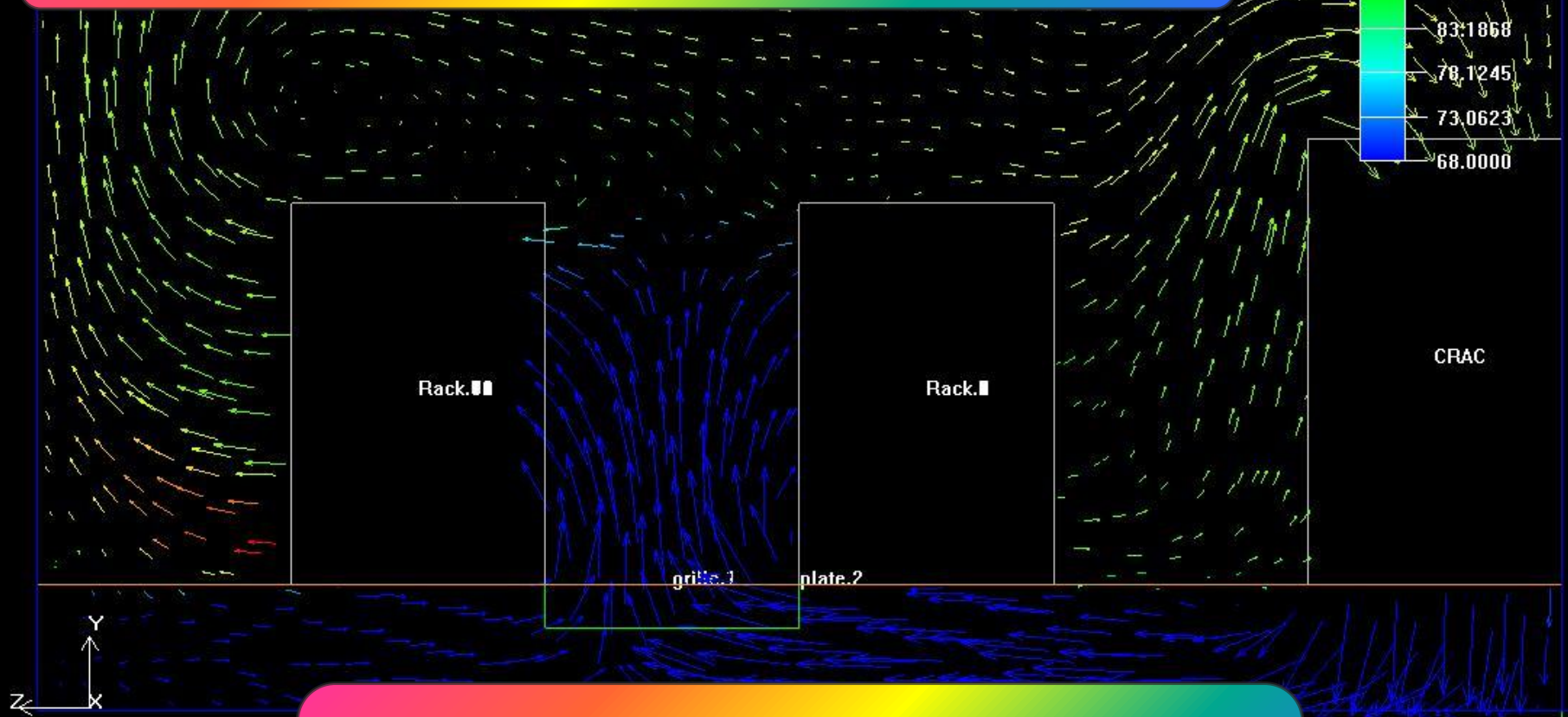
# Logical Controls Architecture

## CRAH Fan Speed = $f(T_{hi} - T_{lo})$

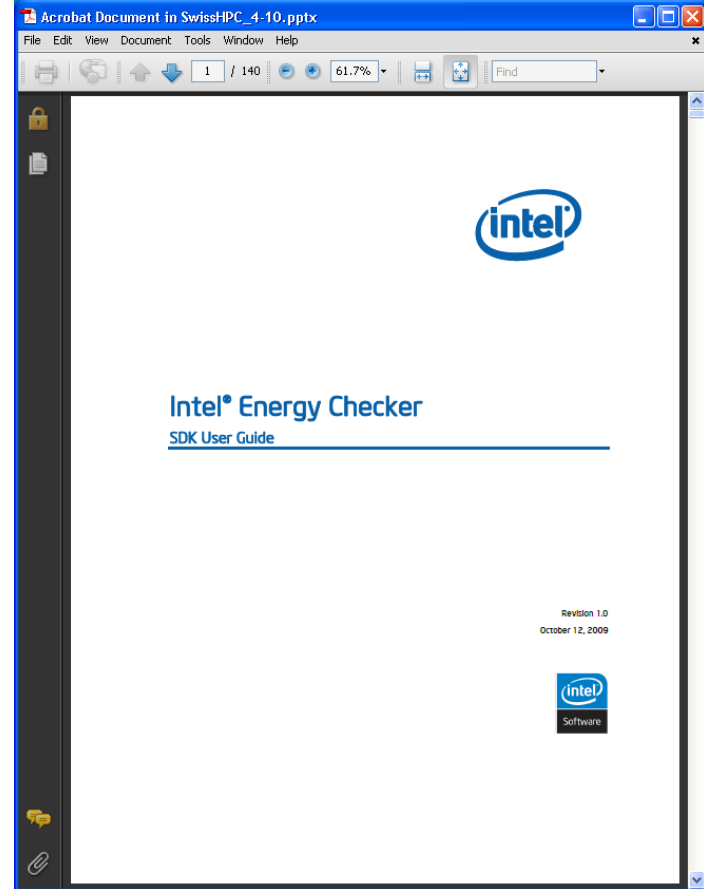
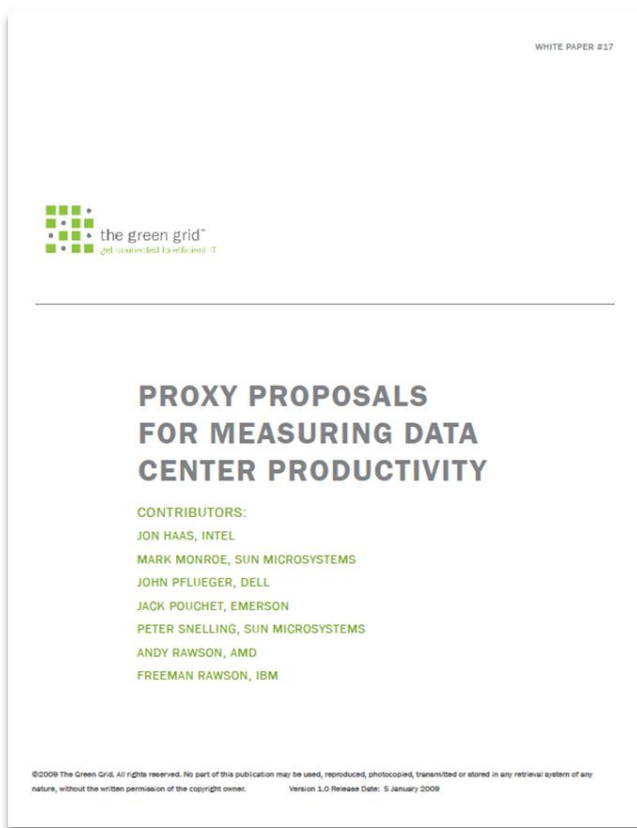


**>75%% Fan Energy Savings  
in our test case evaluation**

**Ideal airflow with minimal recirculation**

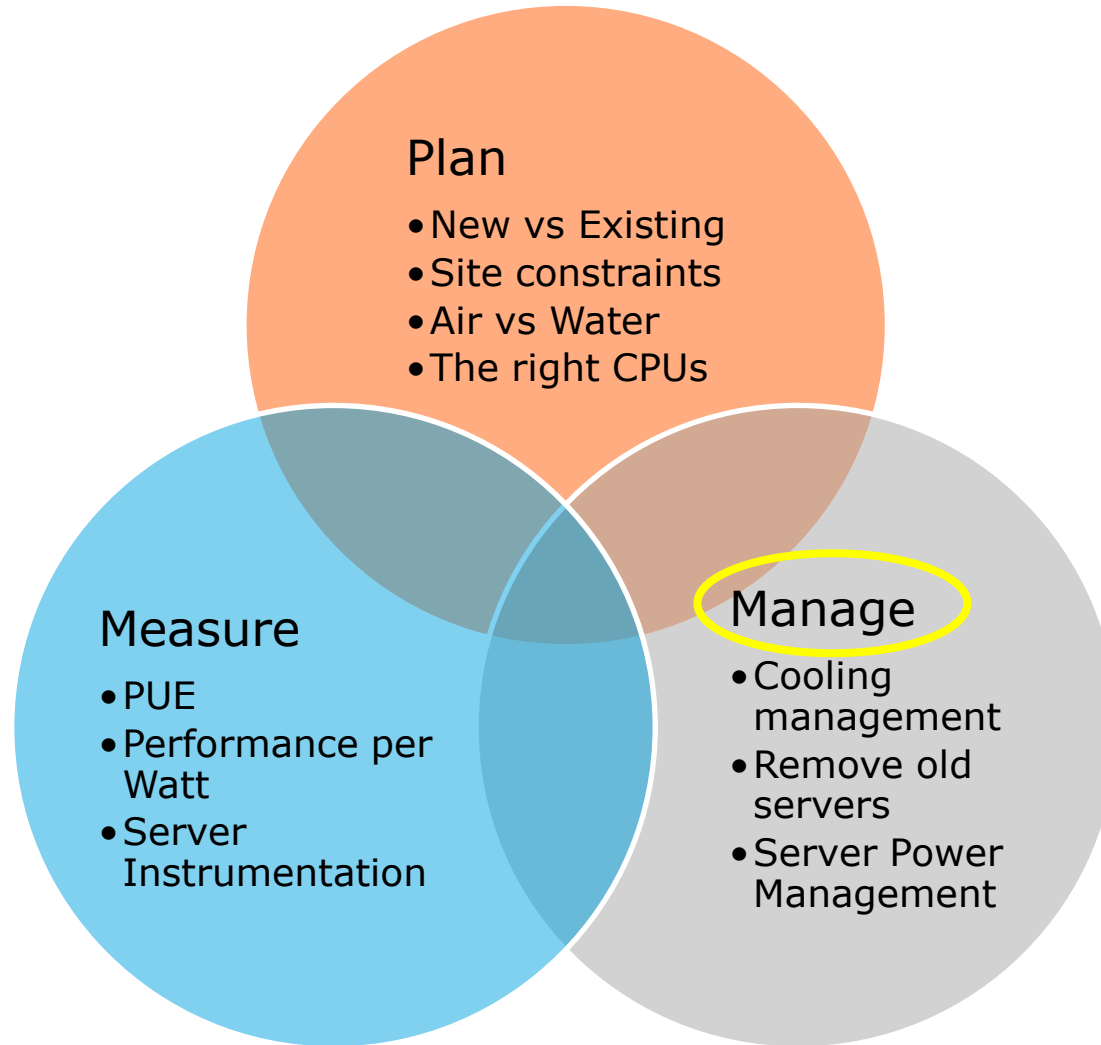


**The HPC Take-Away is the  
instrumentation is there, let's use it**

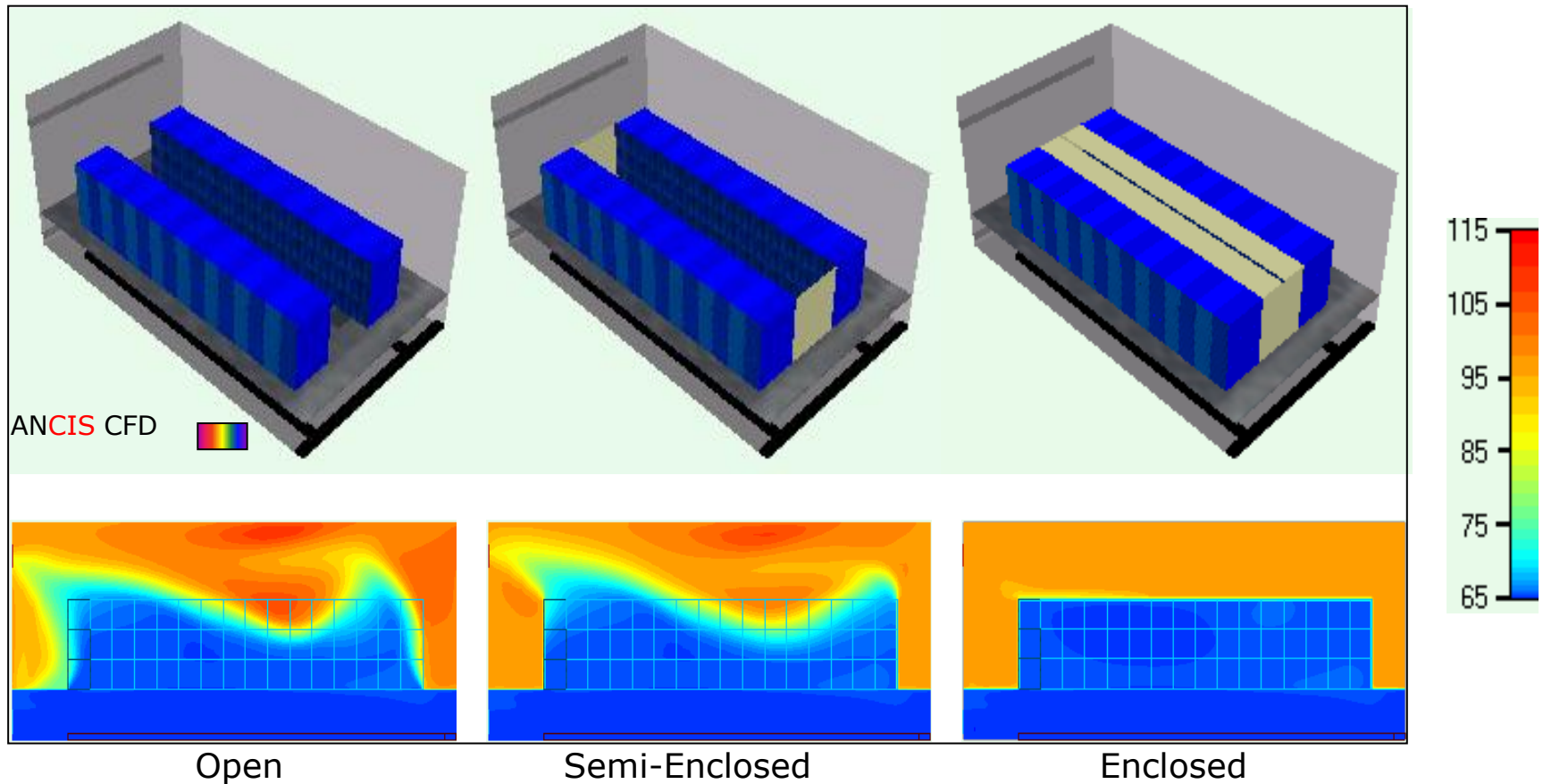


- The Green Grid is working on **Performance per Watt** metrics
- Current Activity with Pacific Northwest National Labs – HPC focus
- Explore Intel's Energy Checker

# How to succeed going forward?



# Why is Hot/Cold Air Segregation Important?



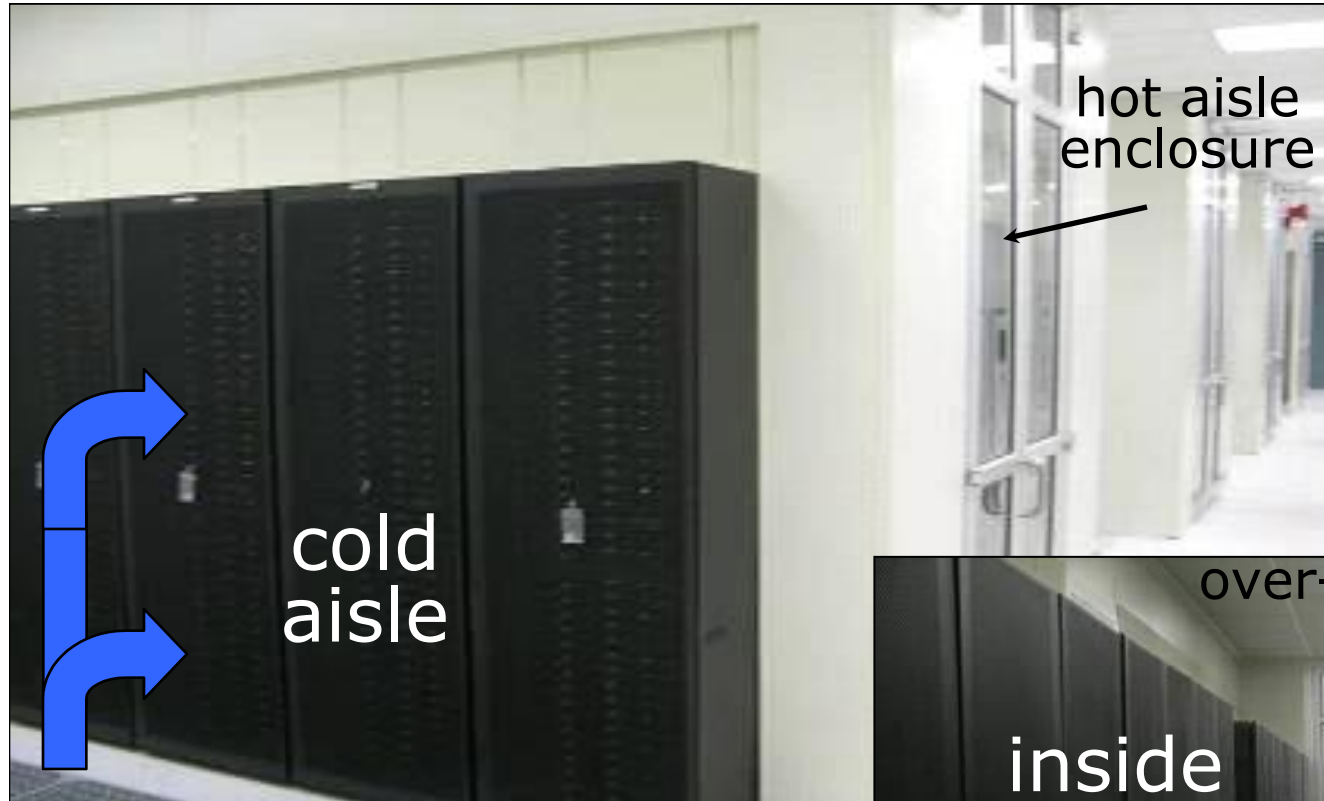


# Intel's SC4 retrofit; cold aisle containment

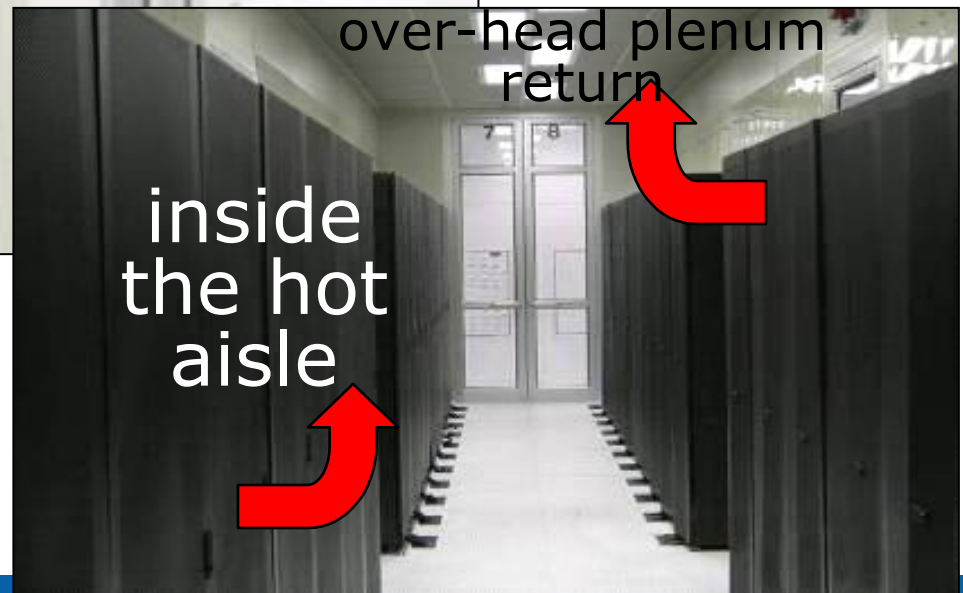


**14 - 22 kW Racks**  
**6000 w/sq m of raised floor**

# State-of-the-art air-flow management



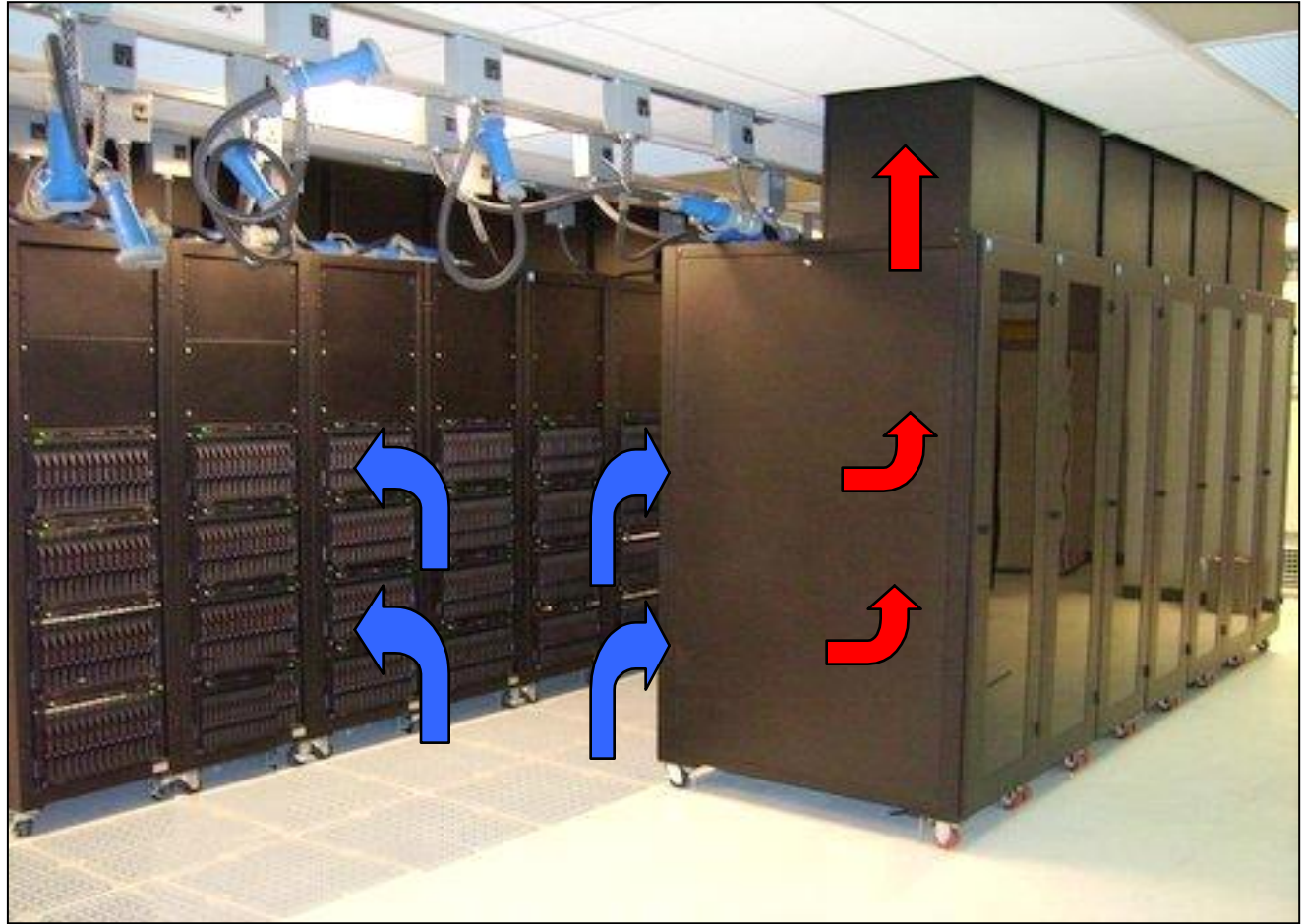
- Entire space becomes the cold aisle
- Raised floor optional



- Best for new construction
- Very efficient when combined with economizer
- Self balancing, low fan energy

# Chimney Cabinets

- Variant of hot aisle enclosures
- Works w/ or w/o raised floor





# Liquid Cooled 30kW racks



Encanto, New Mexico's Cluster

# Air-cooled 30kW cabinets

## w/ chimney cabinets



Air or Water? Doesn't really matter



# Liquid Cooled Racks

- Many shapes and sizes
- Applicable in retrofit data centers as well as new
- Ideal for extending legacy DCs where there is cooling, but limited airflow



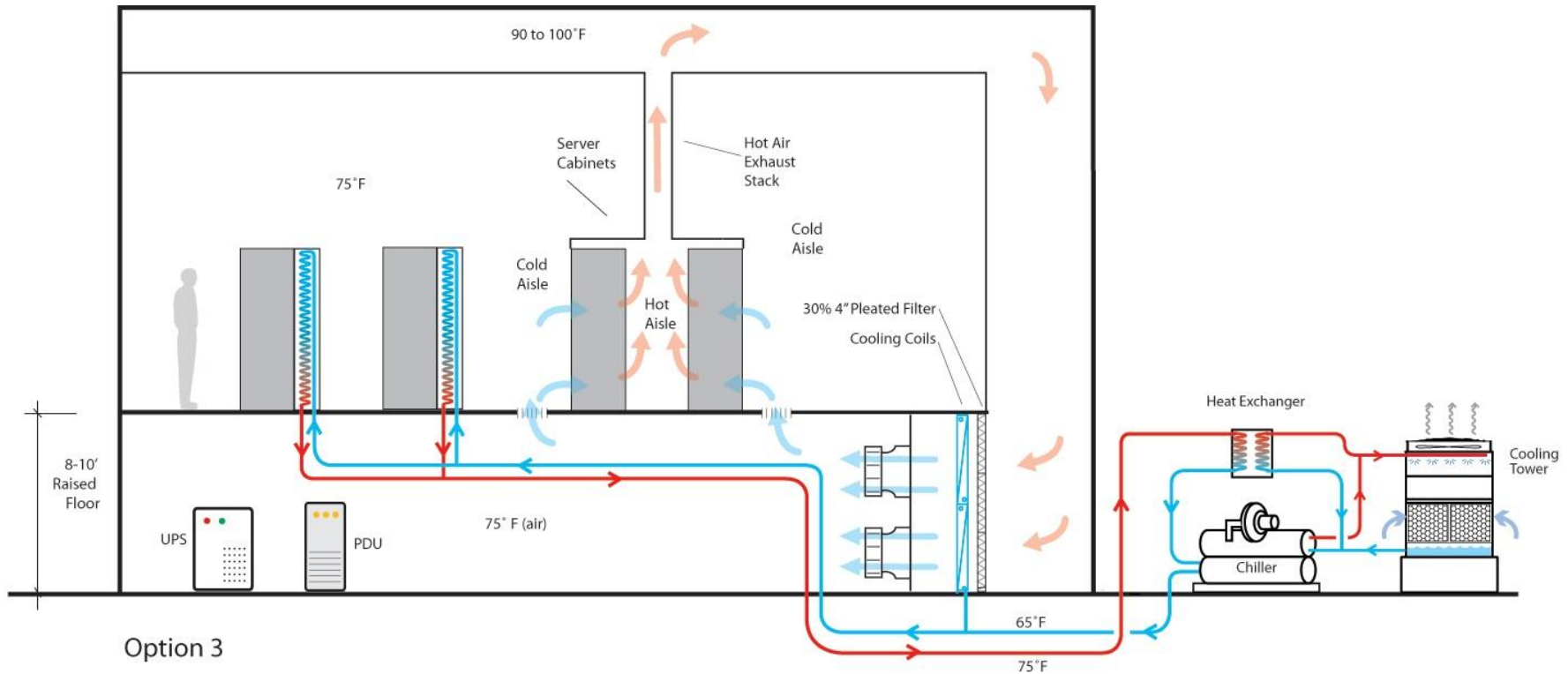
# NCAR-Wyoming Supercomputing Center



Graphic courtesy of H+L Architects & NCAR



# NWSC Cooling Plan



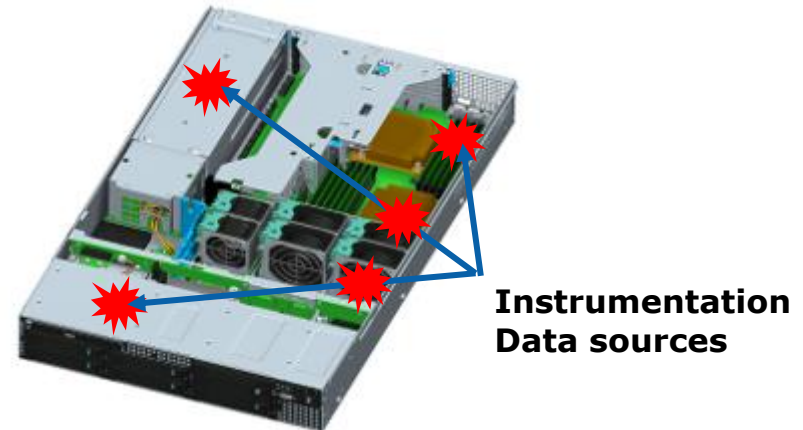
Design by Rumsey Engineers, Inc.



# Intel's Commitment to Instrumentation

- Intel has been delivering and extending instrumentation in its processors and chipsets for years
- With Nehalem-EP, Intel is delivering capabilities that work with other component level instrumentation to extend instrumentation to the platform and data center

Capability	Intel Delivers
Power Reporting	Node Manager
Power Capping	Node Manager
Console Management	Data Center Manager
Simplified Management	Data Center Management Interface



**Delivering Instrumentation Capabilities  
That Address Data Center Issues**

# Introducing Intel Dynamic Node Manager: Streamlined Server Instrumentation

## Hardware and Software Solution Delivered on System Processor

- Streamlines instrumentation design delivery
- Works with server hardware, BIOS, and OS to report and cap system power
- System budgets, specified by external management agent, are communicated over standard interface and can be updated real time
- Available on Intel next generation server platforms Nehalem-EP



- Improves rack density
- Increases performance density
- Delivers load balancing improvements
- Leads to higher availability and TCO

# Planning for the future. State of the art needed tomorrow to maintain affordability

## • Cooling

- Depends on the density split (<40kW, >60kW)
- Airflow management
- Liquid cooled racks
- Economizers
  - Air, water, evaporative
- ASHRAE Extended Envelope
  - 18-27C
  - 5.5-15C dewpoint
- Smarter controls, adaptable cooling

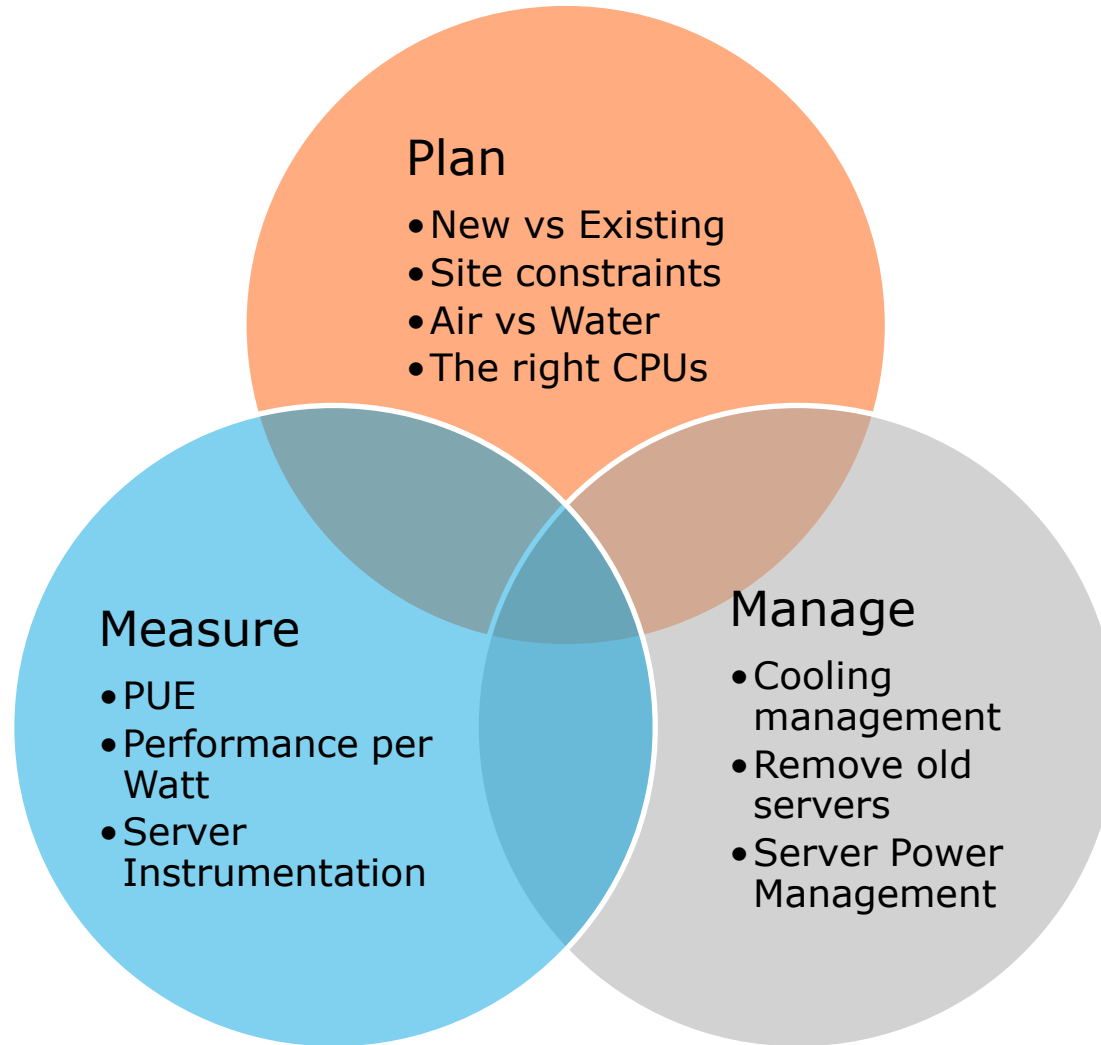
## • Power

- Purpose built power architecture
- More 480/277Vac
- 208Vac or 230Vac still an option
- Smart UPS (only on what you need)
- DC power and HPC don't align due to limited UPS use

It's ***still*** really all about good engineering!



# How to succeed going forward?



Thank You!

Questions?



**back-up**

# Economizer resources

Proceedings of IPACK2009  
InterPACK'09  
July 19-23, 2009, San Francisco, California, USA

## IPACK2009-89358

### EVALUATION OF AIR-SIDE ECONOMIZER USE IN A COMPUTE-INTENSIVE DATA CENTER

Michael K Patterson  
Eco-Technology Program Office  
Digital Enterprise Group  
Intel  
Hillsboro, Oregon, USA

Don Atwood  
Regional Data Center Manager  
Information Technology  
Intel  
Rio Rancho, New Mexico, USA

John G Miner  
IT Innovation Center  
Intel  
Rio Rancho, New Mexico, USA

#### ABSTRACT

Moore's Law continues to drive increased compute capability and greater performance per watt in today's and future server platforms. However the increased demand for compute services has outstripped these gains and the energy consumption in the data center continues to rise. The challenge for the data center operator is to limit the operational costs and reduce the energy required to run the Information and Communications Technology (ICT) equipment and the supporting infrastructure.

The cooling systems can represent a large portion of the energy use in the support infrastructure. There is significant focus in industry today on applying advanced cooling technologies to reduce this energy. One potential solution is the use of air-side economizers in the cooling system. This technology can provide a reduction in cooling energy by being able to maintain the required temperatures in the data center with the mechanical refrigeration turned off, significantly reducing the PUE for the data center.

This paper reviews recent industry activities around the recommended environmental conditions in the data center, the impact to the ICT equipment of air-side economizers, where they can best be applied, and provides data from a case study recently concluded at Intel's site in New Mexico. In that case study servers from an engineering compute data center were split into a standard configuration (closed system, tight

temperature control) and a very aggressive air-side economization section (open system, significant out-door air quantities, moderate temperature control). Both sections performed equally well over a year long on-line test, with significant energy savings potential demonstrated by economizer side.

The American Society of Air-conditioning Heating and Refrigerating Engineers (ASHRAE) has recently published new ICT-vendor consensus-based recommendations for the environmental conditions in data centers. These new limits are discussed in light of the successful experiment run in New Mexico as the revised operational envelop allows a far greater number of hours per year when a data center can be run in "free-cooling" mode to obtain the energy savings.

Server design features as well as lessons learned from the experiment and their applicability to the potential use of air-side economizers is also discussed.

#### INTRODUCTION AND ANALYSIS

Server design continues to evolve and improve, reducing the energy per unit of computation. Moore's Law is continuing to provide society with the best energy efficiency gains of any industry or technology sector in history. Yet these gains come with challenges. Namely the power density available in servers

## Gaseous and Particulate Contamination Guidelines for Data Centers

Whitepaper prepared by ASHRAE Technical Committee (TC) 9.9  
Mission Critical Facilities, Technology Spaces, and Electronic Equipment

This ASHRAE white paper on data center airborne contamination was developed by members of the TC 9.9 committee representing the following IT equipment manufacturers: AMD, Cisco, Cray, Dell, EMC, Hitachi, HP, IBM, Intel, Seagate, SGI, and Sun.

#### Executive Summary

ASHRAE TC 9.9 committee recently published the 2008 ASHRAE Environmental Guidelines for Datacom Equipment which extended the temperature-humidity envelope to provide greater flexibility in data center facility operations, particularly with the goal of reducing energy consumption. The recommended temperature limits are from 18°C (64.4°F) to 27°C (80.6°F). The humidity is limited to less than 60% with the lower and upper dew point temperatures of 5.5°C (41.9°F) and 15°C (59°F).

The recent increase in the rate of hardware failures in data centers high in sulfur-bearing gases, highlighted by the number of recent publications on the subject, led to the need for this white paper that recommends that in addition to temperature-humidity control, dust and gaseous contamination should also be monitored and controlled. These additional environmental measures are especially important for data centers located near industries and/or other sources that pollute the environment.

Effects of airborne contaminations on datacenter equipment can be broken into three main categories: Chemical effects, mechanical effects and electrical effects. Two common chemical failure modes are copper creep corrosion on circuit boards and the corrosion of silver metallization in miniature surface mounted components. Mechanical effects include heat sink fouling, optical signal interference, increased friction, etc. Electrical effects include changes in circuit impedance, arcing, etc. It should be noted that the reduction of circuit board feature sizes and the miniaturization of components, necessary to improve hardware performance, also makes the hardware more prone to attack by contamination in the data center environment. Manufacturers are in a constant struggle to maintain the reliability of their hardware with ever shrinking feature sizes, without taking the added costly measure of hardening all their IT equipment, most of which is not installed in corrosive environments where it can be exposed to higher risk of failure.

Most data centers are well designed and are in areas with relatively clean environments and most contamination is benign. Most data centers should not experience particulate or gaseous contamination related hardware failures. This paper is primarily targeted at a minority of data centers which may have harmful environments arising from the ingress of outdoor particulate and/or gaseous contamination. In some rare instances, contamination has been known to be generated within the data center.

It is incumbent on the data center managers to do their part in maintaining hardware reliability by monitoring and controlling the dust and gaseous contamination in their data centers. Data centers must be kept clean to ISO 14644-1 Class 8. This level of cleanliness can generally be achieved by an appropriate filtration scheme as outlined here:

1. The room air may be continuously filtered with MERV 8 filters as recommended by ANSI/ASHRAE Standard 127-2007, Method of Testing for Rating Computer and Data Processing Room Unitary Air Conditioners.
  2. Air entering a data center may be filtered with MERV 11 or MERV 13 filters as recommended by ASHRAE book titled, "Particulate and Gaseous Contamination in Datacom Environments".
- Sources of dust inside data centers should be reduced. The gaseous contamination should be within the modified ANSI/ISA-71.04-1985 severity level G1 that meets:
1. A copper reactivity rate of less than 300Å/month, and
  2. A silver reactivity rate of less than 300Å/month.

For data centers with higher gaseous contamination levels, gas-phase filtration of the inlet air and the air in the data center is highly recommended.

# 2008 ASHRAE Environmental Guidelines

	High Limit	Low Limit
Temperature	27C (80.6F)	18C (64.4F)
Humidity	Lower of 60% RH or 15C dewpoint	5.5C dewpoint

Opportunities for expanded temperature and humidity operation of data centers to allow less energy use in the cooling system; lowering PUE

